



PolarFire® FPGA and PolarFire SoC FPGA Power-Up and Resets

Introduction

Microchip's PolarFire FPGAs are the fifth-generation family of non-volatile FPGA devices, built on state-of-the-art 28 nm non-volatile process technology. PolarFire FPGAs deliver the lowest power at mid-range densities. PolarFire FPGAs lower the cost of mid-range FPGAs by integrating the industry's lowest power FPGA fabric, lowest power 12.7 Gbps transceiver lane, built-in low power dual PCI Express Gen2 (EP/RP), and, on select data security (S) devices, an integrated low-power crypto co-processor.

Microchip's PolarFire SoC FPGAs are the fifth-generation family of non-volatile SoC FPGA devices, built on state-of-the-art 28 nm non-volatile process technology. The PolarFire SoC family offers industry's first RISC-V based SoC FPGAs capable of running Linux. It combines a powerful 64-bit 5x core RISC-V Microprocessor Subsystem (MSS), based on SiFive's U54-MC family, with the PolarFire FPGA fabric in a single device.

Both PolarFire FPGA and PolarFire SoC FPGAs use advanced power-up circuitry to ensure reliable power-up. When the device is powered on, the Power-on Reset (POR) circuitry and the System Controller ensure a systematic POR. System Controller is responsible for device boot and design initialization. This document describes the entire process of device power-up and resets.

The following table summarizes the power-up and reset states in PolarFire FPGA and PolarFire SoC FPGA families.

Table 1. Power-Up and Reset States

Component	PolarFire FPGA (MPF)	PolarFire SoC FPGA (MPFS)
Power-On	✓	✓
Device Boot	✓	✓
Design and Memory Initialization	✓	✓
• uPROM	✓	✓
• sNVM	✓	✓
• SPI Flash	✓	✓
• eNVM	—	✓
MSS Pre-Boot	—	✓
MSS User Boot	—	✓
Device Reset	✓	✓
MSS Reset	—	✓

References

- For more information about embedded memory blocks, see [PolarFire FPGA and PolarFire SoC FPGA Fabric User Guide](#).
- For more information about MSS booting, see [PolarFire SoC Software Development and Tool Flow User Guide](#).
- For more information about PCIe initialization process, see [PolarFire FPGA and PolarFire SoC FPGA PCI Express User Guide](#).
- For more information about Power-Up to Functional Timing, see [PolarFire FPGA Datasheet](#) or [PolarFire SoC FPGA Advance Datasheet](#).
- For more information about MSS, see [PolarFire SoC FPGA MSS Technical Reference Manual](#).
- For more information on power supply sequencing requirements and recommendations, see [UG0726: PolarFire FPGA Board Design User Guide](#) or [UG0901: PolarFire SoC Board Design Guidelines User Guide](#).

Table of Contents

Introduction.....	1
1. References.....	2
1. Acronyms.....	4
2. Power-Up.....	5
2.1. Power-On.....	5
2.2. Device Boot.....	5
2.3. Design and Memory Initialization.....	6
2.4. MSS Pre-Boot (For PolarFire SoC FPGA Only).....	23
2.5. MSS User Boot (For PolarFire SoC FPGA Only).....	29
2.6. HSIO/GPIO Bank Initialization.....	29
2.7. IO Recalibration.....	31
2.8. Transceiver Initialization.....	32
2.9. User PLLs and DLLs Initialization.....	33
2.10. PCIe Initialization.....	33
2.11. State of Blocks During Power-Up.....	33
3. PolarFire FPGA Resets.....	35
3.1. Hard Resets.....	35
3.2. User Reset Generation Scheme.....	36
4. PolarFire SoC FPGA Resets.....	38
4.1. User Resets.....	38
4.2. MSS Resets.....	39
4.3. User Reset Generation Scheme.....	41
5. Appendix: Power Supplies.....	44
6. Revision History.....	45
The Microchip Website.....	46
Product Change Notification Service.....	46
Customer Support.....	46
Microchip Devices Code Protection Feature.....	46
Legal Notice.....	47
Trademarks.....	47
Quality Management System.....	48
Worldwide Sales and Service.....	49

1. Acronyms

The following table lists the acronyms used in this document.

Table 1-1. List of Acronyms

Acronym	Expanded
AMBA	ARM Advanced Microcontroller Bus Architecture
eNVM	embedded Non-Volatile Memory
MSS	Microprocessor Subsystem
POR	Power on Reset
SCB	System Controller Bus
sNVM	Secure Non-volatile Memory
HSIO	High-speed IO
GPIO	General Purpose IO
PLL	Phase-locked loop
DLL	Delay-locked loop
FIC	Fabric Interface Controller
PCIe	Peripheral Component Interconnect Express

2. Power-Up

The device power-up process includes the following sequential steps:

- [2.1 Power-On](#)
- [2.2 Device Boot](#)
- [2.3 Design and Memory Initialization](#)
- [2.4 MSS Pre-Boot \(For PolarFire SoC FPGA Only\)](#)
- [2.5 MSS User Boot \(For PolarFire SoC FPGA Only\)](#)
- [2.6 HSIO/GPIO Bank Initialization](#)
- [2.8 Transceiver Initialization](#)
- [2.9 User PLLs and DLLs Initialization](#)
- [2.10 PCIe Initialization](#)
- [2.11 State of Blocks During Power-Up](#)

2.1 Power-On

When the device is powered on, the POR circuitry detects voltage ramp-up on the VDD, VDD18, and VDD25 power supply rails using voltage detectors. For a list of power supplies, see [5. Appendix: Power Supplies](#). The System Controller remains in the reset state until the required voltage threshold levels are reached. The System Controller is responsible enabling, or turning on the FPGA fabric and related IOs.

The voltage detectors in the devices are calibrated with a high-level of accuracy to ensure reliable monitoring of minimum threshold levels. For power-supply threshold voltage levels to release POR, see the “Power-on Reset Voltages” section in respective [PolarFire FPGA Datasheet](#) or [PolarFire SoC FPGA Advance Datasheet](#). The device boot starts after a programmable delay of 20 μ s to 50 ms and also after the voltage supply rails reach their respective threshold voltage levels.

In both the device families, there are separate voltage detectors to monitor IO bank supplies. During POR, the dedicated IO bank is powered-up, the serial transceivers and the fabric are powered down, and HSIO/GPIO banks are tri-stated. Separate detectors in the associated IO bank controller (for Bank 3) detect when the VDDI3 is at the level required to allow enabling the inputs and subsequently (after a delay of 200 ns) the outputs of the dedicated IO bank (including SPI configuration and JTAG IO).

For more information on power supply sequencing requirements and recommendations, see the “Core Power Supply Operations” section, in respective [UG0726: PolarFire FPGA Board Design User Guide](#) or [UG0901: PolarFire SoC Board Design Guidelines User Guide](#).

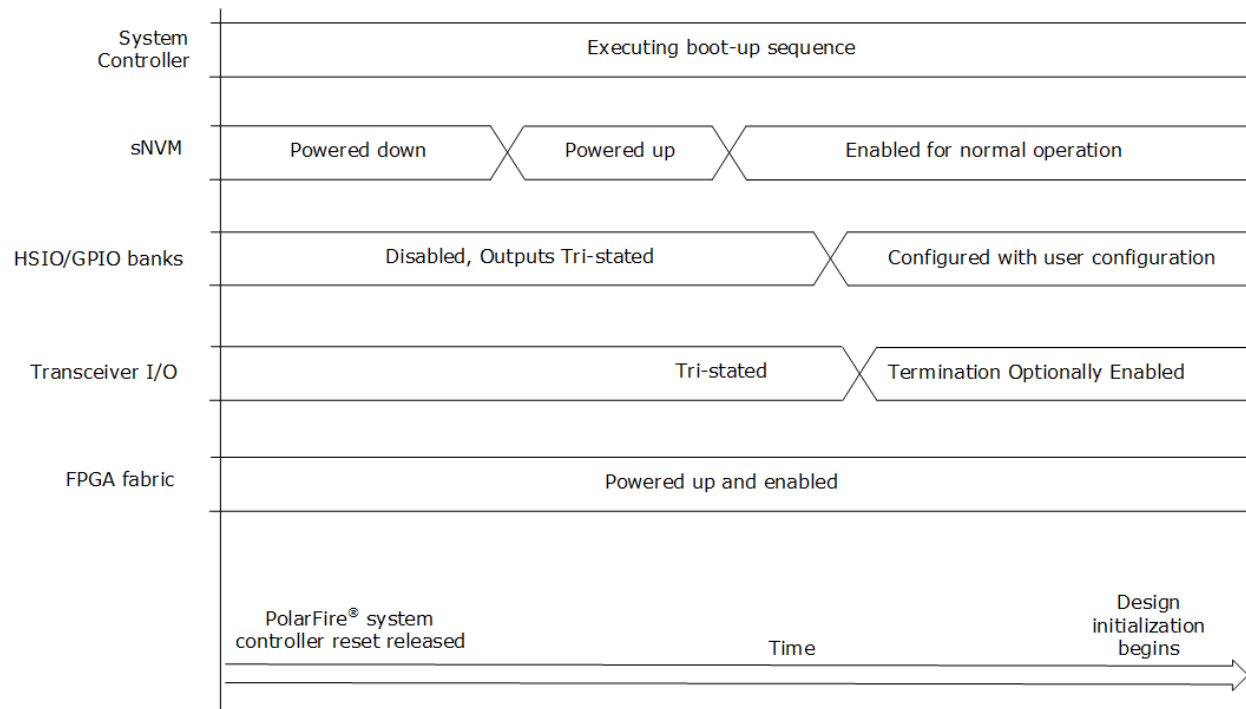
2.2 Device Boot

After POR circuitry releases the System Controller from reset, the device boot-up procedure is executed by the System Controller to bring-up FPGA fabric and related IOs. The System Controller always executes the same device boot-up sequence irrespective of the user design.

The following events occur during device boot-up:

- sNVM is powered up and enabled for normal operation.
- Transceiver IOs are enabled.
- User voltage detectors are enabled.
- FPGA fabric is powered-up and enabled.
- HSIO and GPIO banks are configured based on the user configuration in the Libero[®] SoC
 - Only GPIO can be used before calibration.
- MSS is powered down and MSSIOs are tri-stated (for PolarFire SoC FPGA only).

The following illustration shows the boot-up sequence for a programmed PolarFire FPGA device.

Figure 2-1. Device Boot-Up for PolarFire FPGA

2.3 Design and Memory Initialization

When the device boot is completed, the state of the RAM blocks (LSRAMs and μ SRAMs) zeros after power-up. In both the device families, the fabric RAM blocks can be initialized with known values, if desired. PCIe and XCVR blocks used in the design are initialized with the user configuration data at power-up. The System Controller performs the design and memory initialization during the power-up sequence. The memory initialization data can be stored in μ PROM, sNVM, or an external SPI Flash. The storage location of the initialization data is selected during the Libero design flow. The initialization data can be encrypted for storing in external SPI Flash.

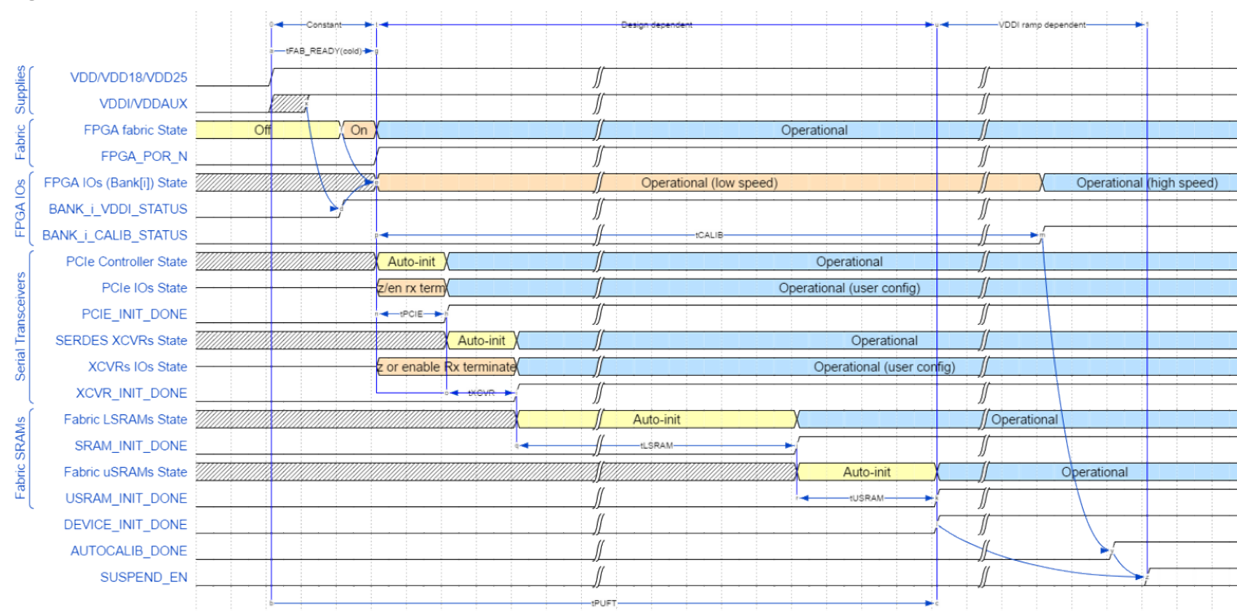
The following figure shows the sequence in which the fabric, PCIe, Transceiver, LSRAMs, and μ SRAMs are automatically initialized. The sequence is customized depending on the resources instantiated in the user design. For example, the PCIE_INIT_DONE will not assert if the user design does not contain PCIe. As a result, the sequence skips the PCIe initialization and moves to the next step. At this stage in PolarFire SoC FPGA device, the MSS remains in reset.

In Libero SoC, memory initialization can be done using any of the following methods:

- Importing the content file using the **fabric RAMs** tab of the **Configure Design Initialization Data and Memories** option after Place and Route is performed. For more information, see [2.3.5 How To Set Up Design and Memory Initialization](#).
- Importing the content file using the **LSRAM and μ SRAM Configurator** before Place and Route. For more information, see [2.3.7 RAM Initialization Before Place and Route](#).

The user can monitor the design initialization status using the Initialization Monitor.

Figure 2-2. Power-up To Functional Time



The typical PUF_T takes about 100 clock cycles to assert SUSPEND_EN after Device Initialization (Device_Init_done) is done. For more information about typical PUF_T, see respective [PolarFire FPGA Datasheet](#) or [PolarFire SoC Advance Datasheet](#).

The total power-up to functional time is as shown in the following equation:

$$t_{PUFT} = t_{FAB_READY(cold/warm)} + \max((t_{PCIE} + t_{XCVR} + t_{LSRAM} + t_{USRAM}), t_{CALIB})$$

PUFT is variable depending on the design configuration.

Notes:

- Both the device families have built-in tamper detection features to monitor voltage supplies and flags to detect minimum or maximum threshold values. These flags are valid only after design initialization, and not during POR.
- Power-up To Functional Time** is based on the case where VDDI/VDDAUX of IO banks are powered either before or after VDD/VDD18/VDD25. The IO bank enable time is measured from the assertion time of VDD/VDD18/VDD25. If VDDI/VDDAUX of IO banks are powered sufficiently after VDD/VDD18/VDD25, then the IO bank enable time is measured from the assertion of VDDI/VDDAUX. In this case, IO operation is indicated by the assertion of BANK_#_VDDI_STATUS, rather than being measured relative to FABRIC_POR_N negation.
- The assertion of AUTOCALIB_DONE can occur before or after the assertion of DEVICE_INIT_DONE. The time taken for the assertion of AUTOCALIB_DONE depends on:
 - The time when VDDI/VDDAUX is up after VDD/VDD18/VDD25 is powered on.
 - The ramp times of VDDI of each IO bank designated for auto-calibration.
 - How much auto-initialization is to be performed for the PCIe, SerDes transceivers and fabric LSRAMs.
 - If any of the IO banks specified for auto-calibration do not have their VDDI/VDDAUX powered on within the auto-calibration timeout window, then it auto-calibrates whenever VDDI/VDDAUX is subsequently powered on. To obtain an accurate calibration on such IO banks, it is necessary to initiate a re-calibration (using CALIB_START from fabric).
- SUSPEND_EN asserts (if the suspend mode is enabled) when DEVICE_INIT_DONE or AUTOCALIB_DONE is asserted.

The following signals are asserted during the design initialization:

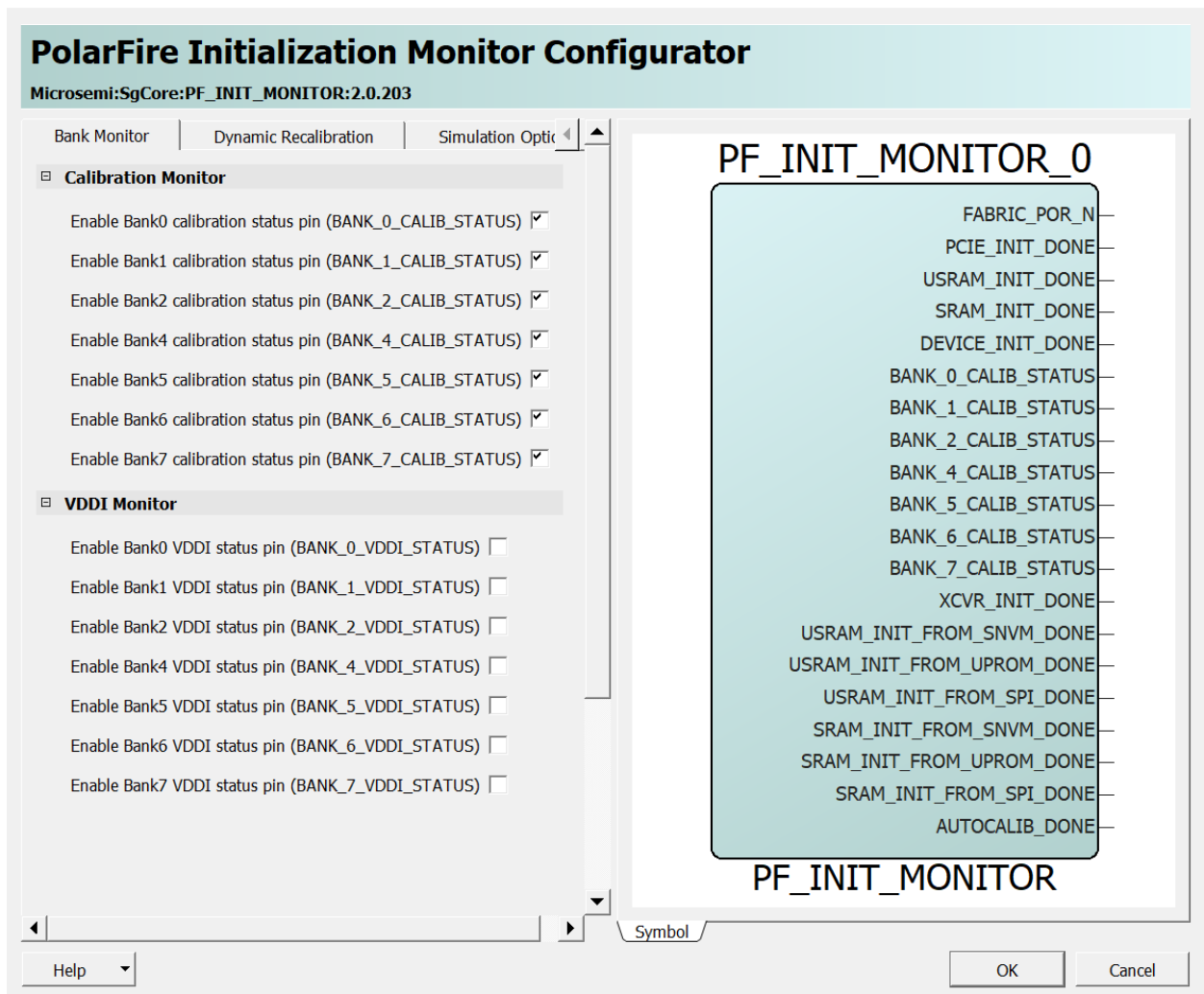
- DEVICE_INIT_DONE**: asserted once the execution of design initialization is complete and remains high. If the PFSoc_INIT_MONITOR IP output DEVICE_INIT_DONE is used as INIT_DONE input to the CORERESET_PF IP, then MSS gets operational after DEVICE_INIT_DONE. Also, MSS can be configured without using DEVICE_INIT_DONE, which is independent of PFSoc_INIT_MONITOR IP. This signal is used as source for generating system-level reset and CORERESET_PF IP controls the MSS reset.

-
- FABRIC_POR_N: de-asserted when the fabric is operational.
 - PCIE_INIT_DONE: used by fabric logic to hold PCIe-related fabric logic in reset until the PCIe controller is initialized. PCIE_INIT_DONE is asserted after initializing the PCIe lane instances placed in the PCIe quad. If only XCVR lanes are placed in the PCIe quad, only XCVR_INIT_DONE is asserted.
 - XCVR_INIT_DONE: asserted when the XCVR block is initialized.
 - SRAM_INIT_DONE: asserted when the LSRAM blocks are initialized.
 - USRAM_INIT_DONE: asserted when the μ SRAM blocks are initialized.
 - BANK_#_CALIB_STATUS: This signal can be used by user logic to determine if the calibration completes for each IO banks. # denotes the bank number (0,1, 7, 8, and 9).
 - BANK_#_VDDI_STATUS: This signal can be used to monitor status of VDDI supply on specific IO banks. This signal is the output signal from the INIT_MONITOR IP if any of the corresponding bank is selected. # denotes the bank number (0,1, 7, 8, and 9).
 - SRAM_INIT_FROM_SNVM_DONE: asserted when SRAM is initialized from sNVM.
 - USRAM_INIT_FROM_SNVM_DONE: asserted when USRAM is initialized from sNVM.
 - SRAM_INIT_FROM_UPROM_DONE: asserted when SRAM is initialized from μ PROM.
 - USRAM_INIT_FROM_UPROM_DONE: asserted when USRAM is initialized from μ PROM.
 - SRAM_INIT_FROM_SPI_DONE: asserted when SRAM is initialized from SPI.
 - USRAM_INIT_FROM_SPI_DONE: asserted when USRAM is initialized from SPI.

PolarFire Initialization Monitor

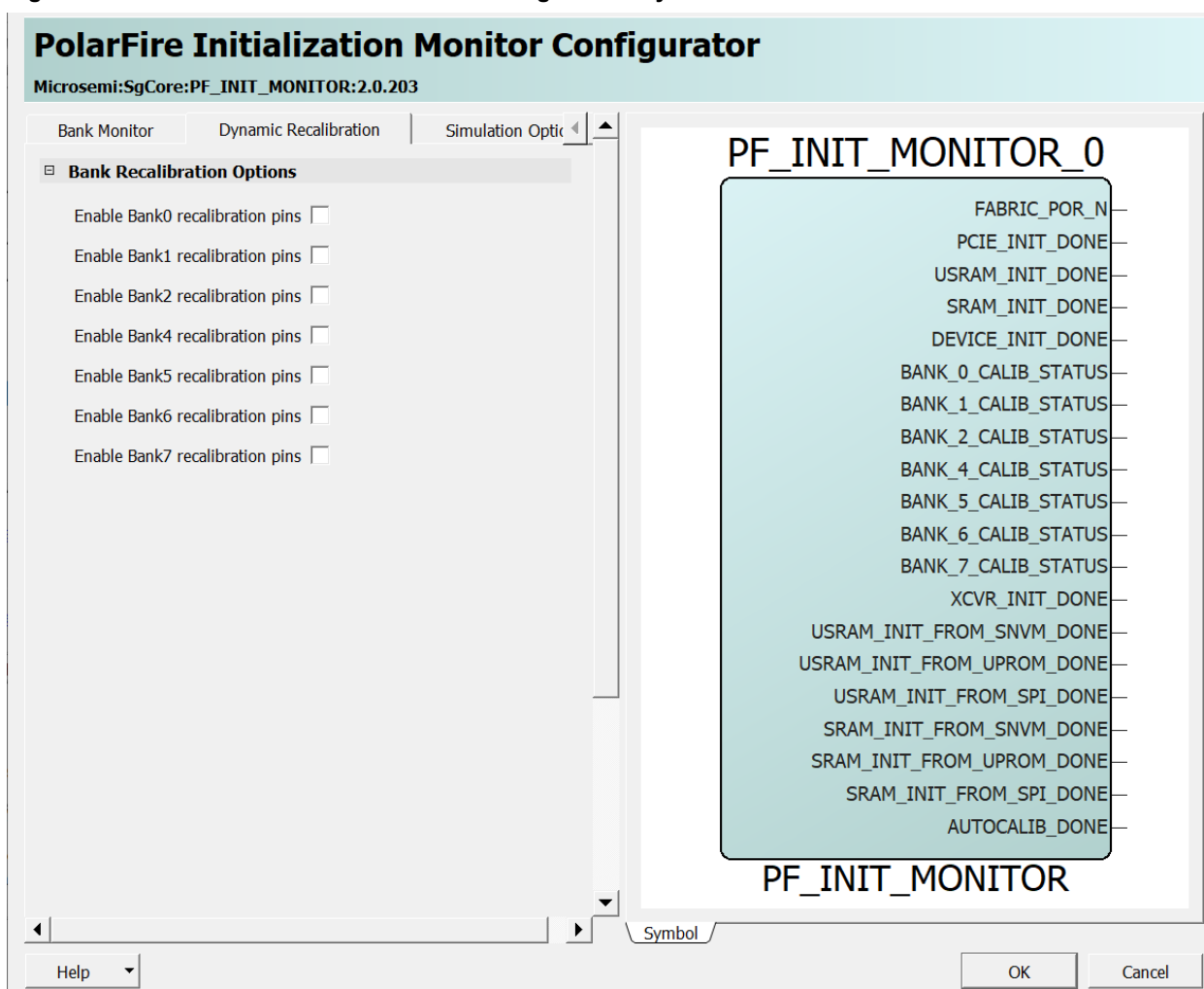
PolarFire Initialization Monitor (PF_INIT_MONITOR) macro is available in the **IP Catalog** under **Clock and Management** as shown in the following figure.

Figure 2-3. PolarFire Initialization Monitor Configurator



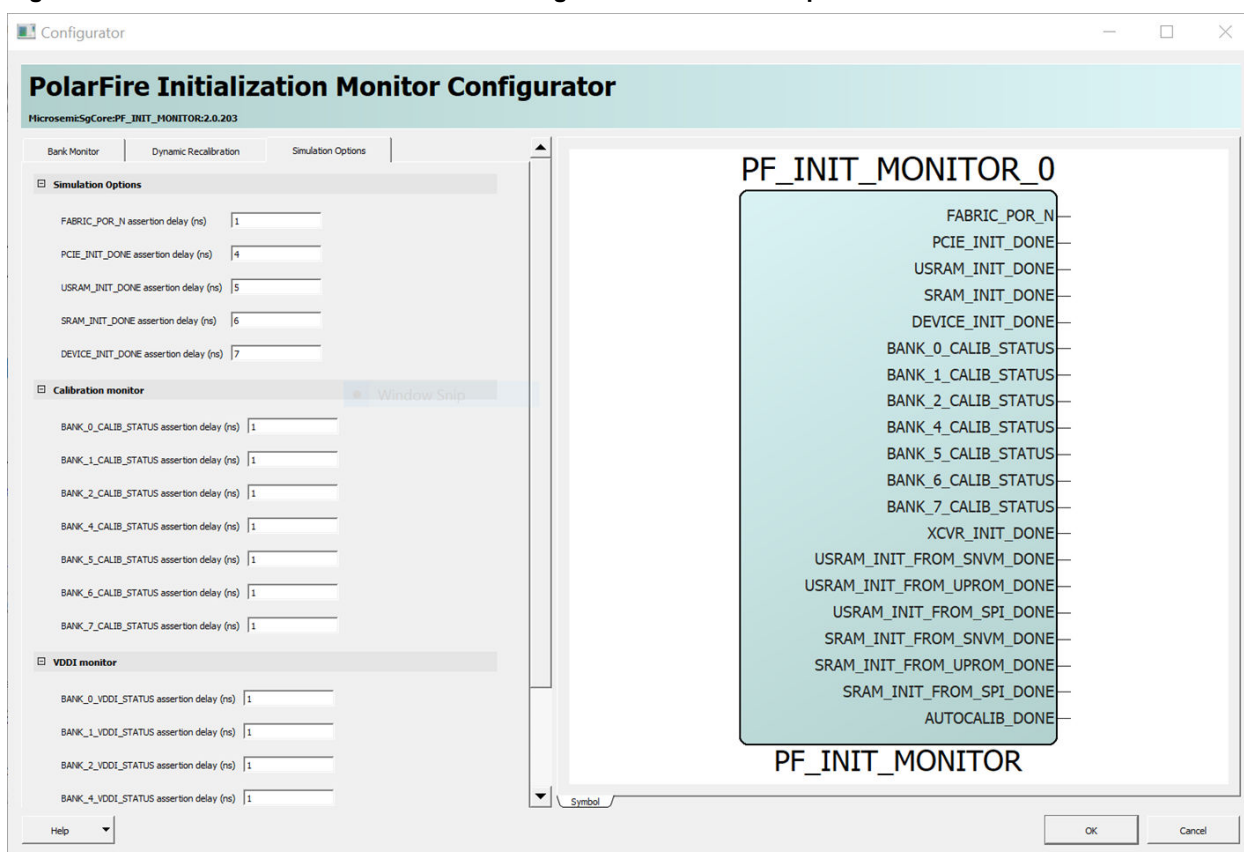
The following figure shows the **Dynamic Recalibration** tab.

Figure 2-4. PolarFire Initialization Monitor Configurator - Dynamic Recalibration



PolarFire Initialization Monitor provides simulation support. Use the **Simulation Options** tab to specify the time of releasing the output signals from the zero time instance. The following figure shows the **Simulation Options** tab.

Figure 2-5. PolarFire Initialization Monitor Configurator - Simulation Options

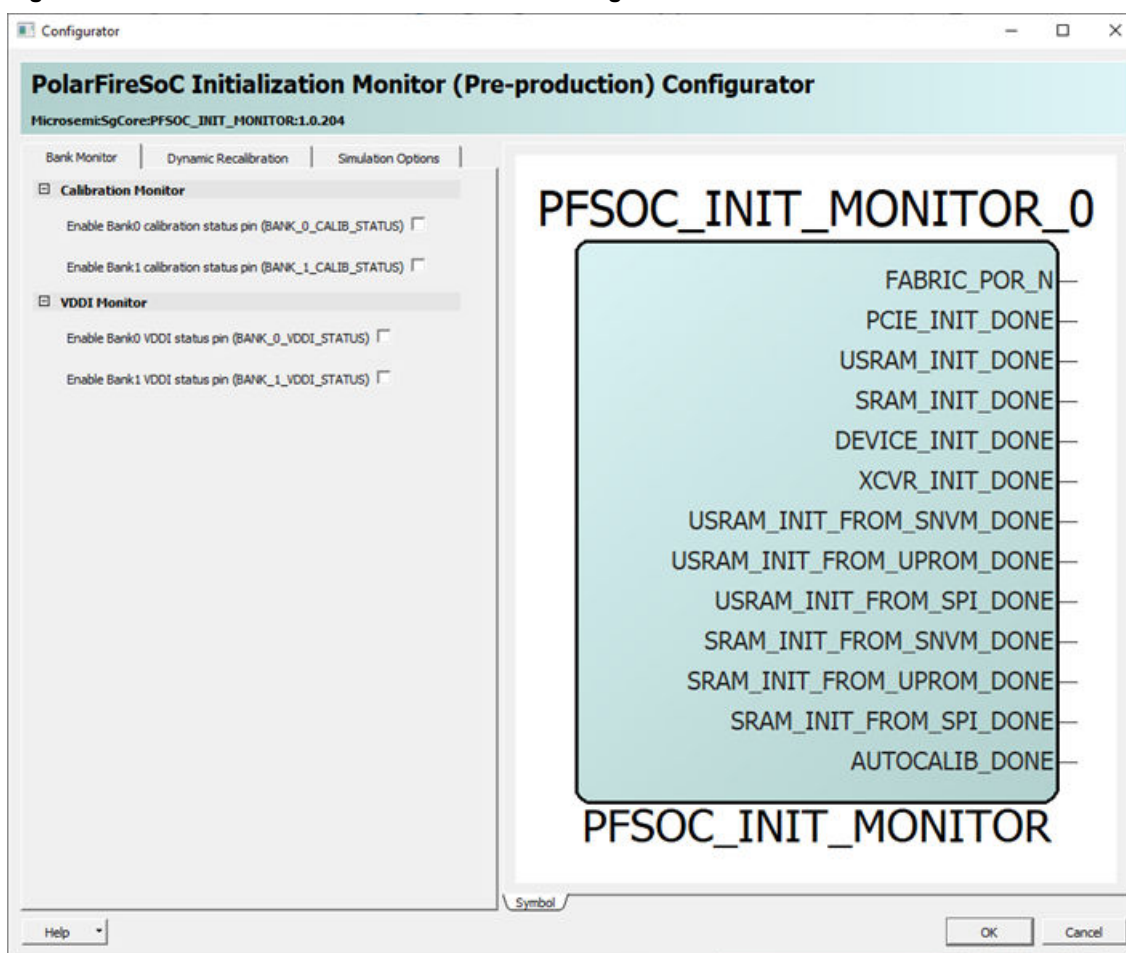


Note: IOs must be calibrated before initiating the training logic of the DDR controller. This requires generating a reset signal by ANDing the DEVICE_INIT_DONE and BANK_#_CALIB_STATUS signals of the PFSOC_INIT_MONITOR IP. BANK_# refers to the BANK where DDR subsystem is placed.

PolarFire SoC Initialization Monitor

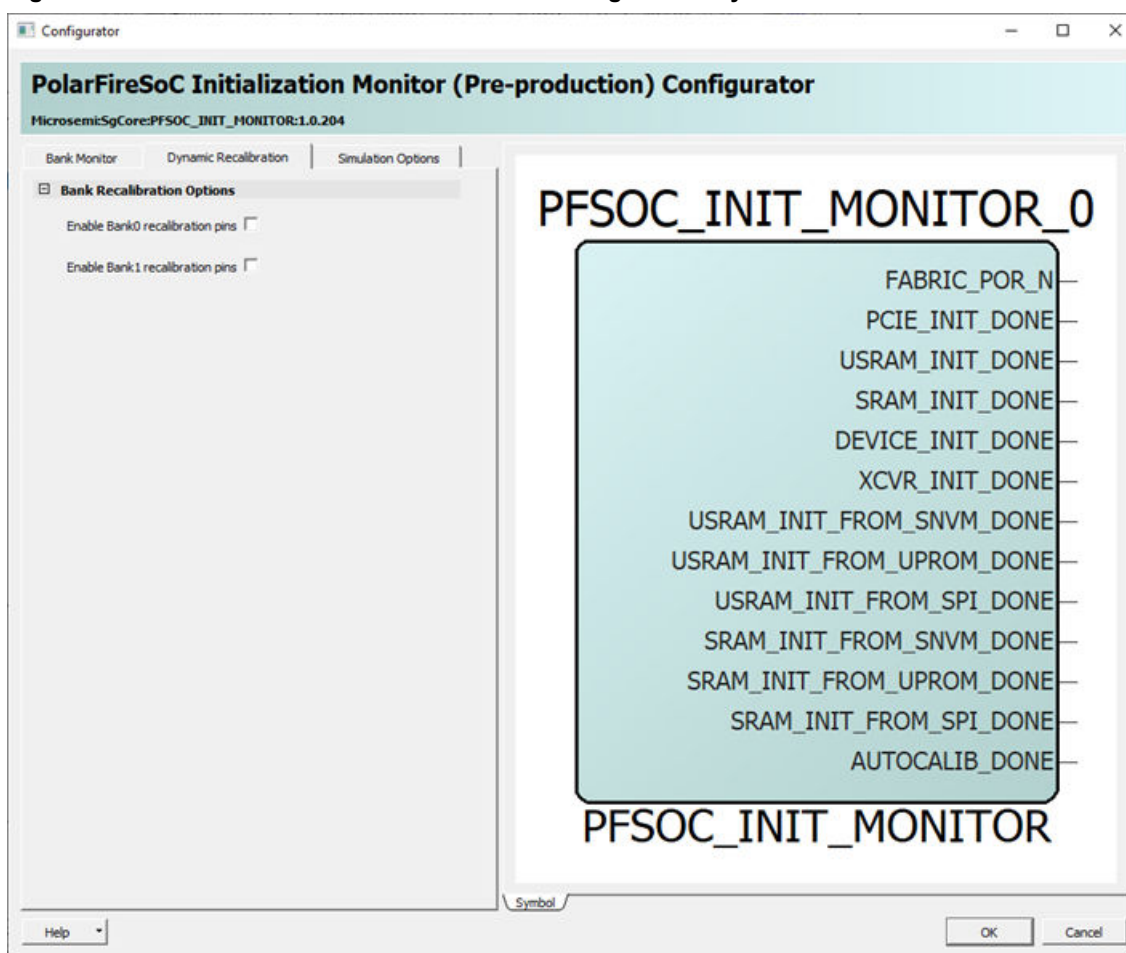
PolarFire SoC Initialization Monitor (PFSOC_INIT_MONITOR) macro is available in the **IP Catalog** under **Clock and Management** as shown in the following figure.

Figure 2-6. PolarFire SoC Initialization Monitor Configurator



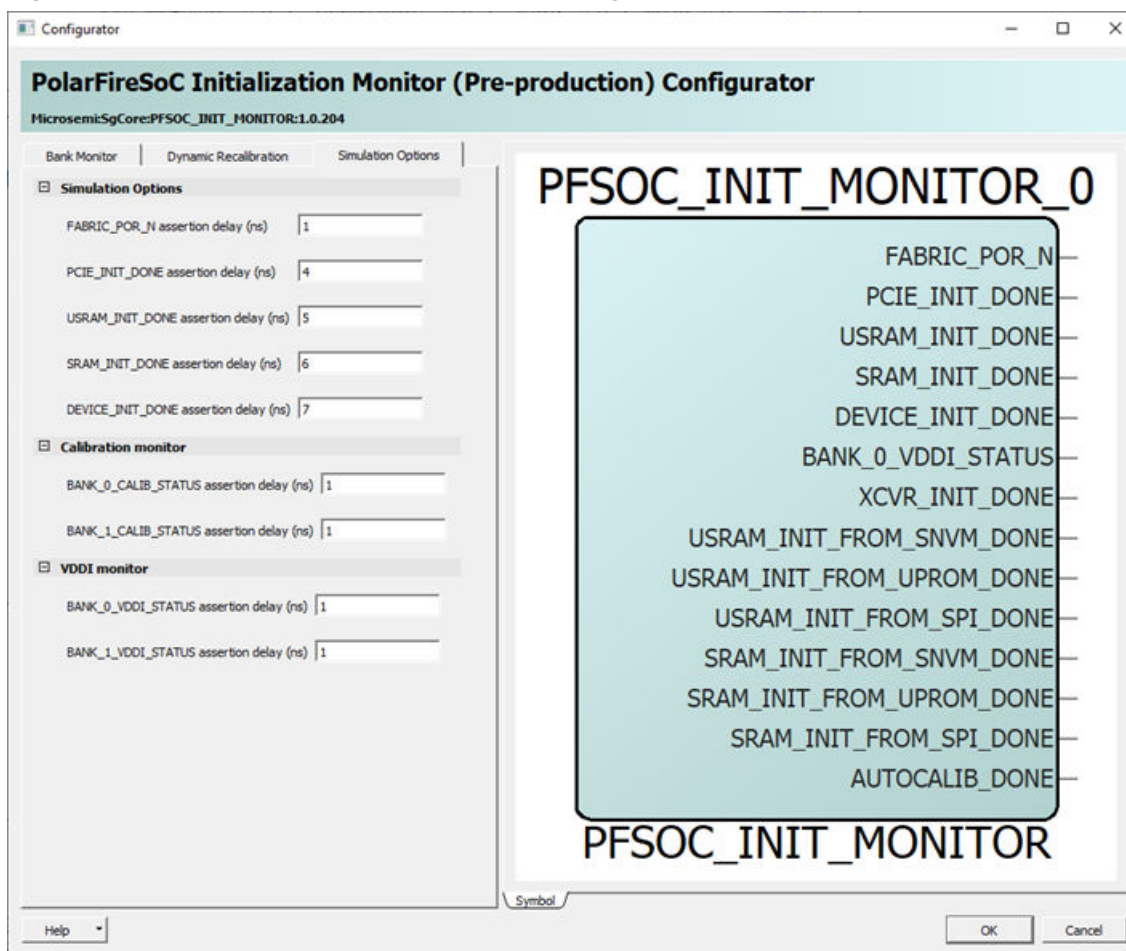
The following figure shows the **Dynamic Recalibration** tab.

Figure 2-7. PolarFire SoC Initialization Monitor Configurator - Dynamic Recalibration



PolarFire SoC Initialization Monitor provides simulation support. Use the **Simulation Options** tab to specify the time of releasing the output signals from the zero time instance. The following figure shows the **Simulation Options** tab.

Figure 2-8. PolarFire SoC Initialization Monitor Configurator - Simulation Options



Note: IOs must be calibrated before initiating the training logic of the DDR controller. This requires generating a reset signal by ANDing the DEVICE_INIT_DONE and BANK_#_CALIB_STATUS signals of the PFSOC_INIT_MONITOR IP. BANK_# refers to the BANK where DDR subsystem is placed.

2.3.1 Secured Non-Volatile Memory (sNVM)

Each device has 56 Kbytes of sNVM, organized into 221 pages of 236 or 252 bytes depending on whether the data is stored as plain text or encrypted/authenticated data. It can be accessed through system service calls to the System Controller. Pages within the sNVM can be marked as ROM during bit-stream programming. The sNVM content can be used to initialize LSRAMs and μ SRAMs with secure data.

The following formulas applies where there is at least one LSRAM or USRAM to be auto-initialized in the user design, giving a duration in milliseconds.

$$t_{\text{LSRAM_pt_SNVM}} = ((14.0875 + (541.4125 \times L)) / 1000) \pm 6\%$$

$$t_{\text{USRAM_pt_SNVM}} = ((14.0875 + (29.325 \times L)) / 1000) \pm 6\%$$

Where,

L = Number of LSRAMs to be auto-initialized

U = Number of small SRAMs to be auto-initialized

Note: pt in "tLSRAM_pt_SNVM" and "tUSRAM_pt_SNVM" refers to "plaintext".

2.3.2 Embedded Non-Volatile Memory (eNVM) (For PolarFire SoC FPGA Only)

PolarFire SoC FPGA devices include one embedded non-volatile memory (eNVM) block size of 128 KB. eNVM supports Single error correction and dual error detection (SECDED) protected, High Data Retention Time. For more information, see [PolarFire FPGA and PolarFire SoC FPGA Security User Guide](#).

2.3.3 μ PROM

Both the device families have a micro programmable read-only memory (μ PROM) row located at the bottom of the fabric, providing up to 513 Kbytes of non-volatile, read-only memory. The address bus is 16-bit wide and the read data bus is 9-bit wide. Fabric logic has access to the entire μ PROM data.

The following formulas apply where there is at least one LSRAM or USRAM to be auto-initialized in the user design, giving a duration in milliseconds.

$$t_{\text{LSRAM_pt_UPROM}} = ((30.1325 + (663.7125 \times L)) / 1000) \pm 6\%$$

$$t_{\text{USRAM_pt_UPROM}} = ((30.1325 + (28.75 \times U)) / 1000) \pm 6\%$$

Where,

L = Number of LSRAMs to be auto-initialized

U = Number of small SRAMs to be auto-initialized

Note: pt in "tLSRAM_pt_UPROM" and "tUSRAM_pt_UPROM" refers to "plaintext" .

2.3.4 External SPI Flash

The SPI Flash memory interfaces with the System Controller's SPI interface and can store the programming images. The System Controller supports devices from vendors like Micron, Winbond, and Spansion.

Fabric SRAM (tLSRAM and tUSRAM) in SPI Flash can be initialized using Plaintext Initialization Data, Authenticated Plaintext Initialization Data, and Authenticated Encrypted Initialization Data.

If user design does not require the auto-initialization of any large FPGA fabric SRAMs, the tLSRAM parameter is zero. If user design does not require the auto-initialization of any small FPGA fabric SRAMs (USRAMs), the tUSRAM parameter is zero.

2.3.4.1 Plaintext Initialization Data Without Authentication

The following formulas apply where there is at least one LSRAM or USRAM to be auto-initialized in the user design from SPI Flash, giving a duration in milliseconds.

$$t_{\text{LSRAM_pt}} = [(((\text{ROUNDUP}(4.034 \times L) + 1) \times 8192 / f) + (130 \times L)) / 1000] + 1 \pm 6\%$$

$$t_{\text{USRAM_pt}} = [(((\text{ROUNDUP}(0.144 \times U) + 1) \times 8192 / f) + (25 \times U)) / 1000] + 1 \pm 6\%$$

Where,

L = Number of LSRAMs to be auto-initialized

U = Number of small SRAMs to be auto-initialized

f = Frequency of the SPI clock in MHz

Note: pt in "tLSRAM_pt" and "tUSRAM_pt" refers to "plaintext" .

2.3.4.2 Authenticated Plaintext Initialization Data

If authentication of the plaintext initialization data is selected, an additional 103 ms \pm 6% must be added to the tLSRAM_pt and tUSRAM_pt timing parameters.

Note: pt in "tLSRAM_pt" and "tUSRAM_pt" refers to "plaintext" .

2.3.4.3 Authenticated Encrypted Initialization Data

The following formula calculates the additional time required for LSRAM to perform the encryption.

$$t_{\text{LSRAM_enc}} = t_{\text{LSRAM_pt}} + t_{\text{LSRAM_auth}} + ((\text{ROUNDUP}((L \times 2560) / 1024, 1) + 1) \times 1024 \times 8 / \text{Dlsram}) / 1000$$

Where, pt in "tLSRAM_pt" refers to "plaintext".

Note: Dlsram depends on the SPI SCK frequency.

The following table lists the LSRAM encrypted data divisor settings.

Table 2-1. LSRAM Encrypted Data Divisor Settings

SPI_SCK frequency (MHz)	Dlsram
13.33	180
20	30
40	15

The following formula calculates the additional time required for USRAM to perform the encryption.

$$t_{\text{USRAM_enc}} = t_{\text{USRAM_pt}} + t_{\text{USRAM_auth}} + ((\text{ROUNDUP}((U \times 2560) / 1024, 1) + 1) \times 1024 \times 8 / \text{Dusram}) / 1000$$

Where,

- $t_{\text{LSRAM_pt}} = t_{\text{LSRAM}}$
- $t_{\text{USRAM_pt}} = t_{\text{USRAM}}$
- auth in "tLSRAM_auth" and "tUSRAM_auth" refers to "Authenticated Plaintext".
- pt in "tUSRAM_pt" refers to "plaintext".
- $t_{\text{LSRAM_auth}} = t_{\text{USRAM_auth}} = 103\text{ms} \pm 6\%$.

Note: Dusram depends on the SPI SCK frequency.

The following table lists the USRAM encrypted data divisor settings.

Table 2-2. USRAM Encrypted Data Divisor Settings

SPI_SCK frequency (MHz)	Dlsram
20	45
40	20

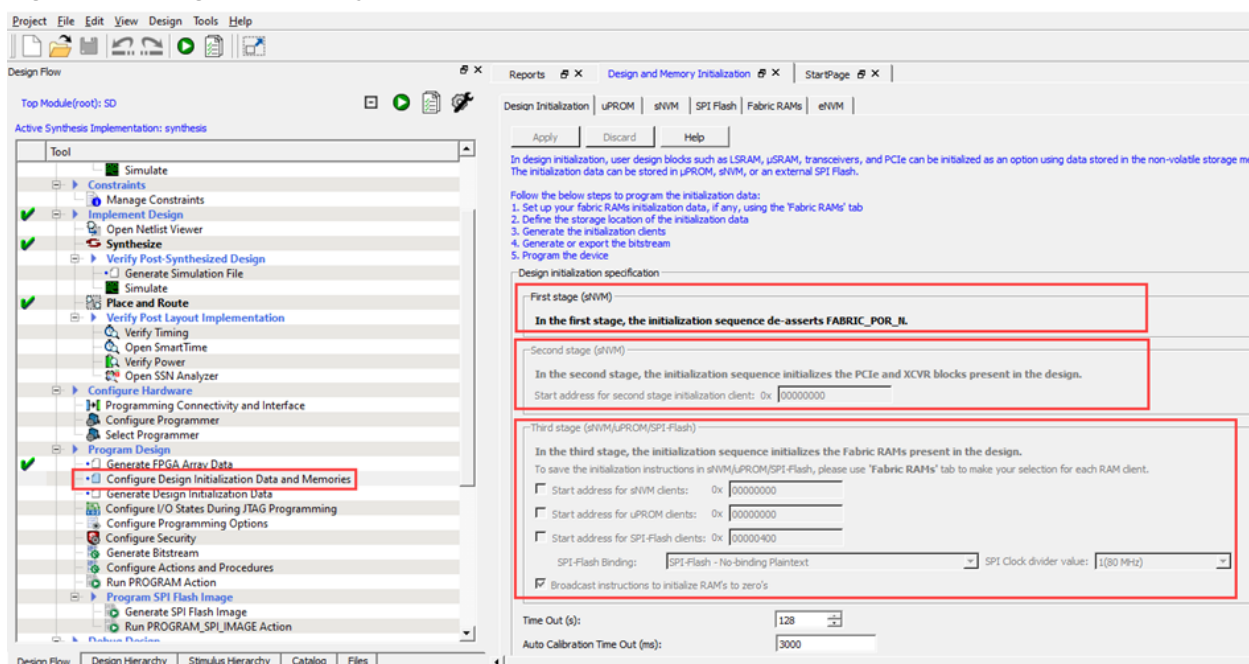
For SPI_SCK frequency of 13.3 MHz, the formula is as follows:

$$t_{\text{USRAM_enc}} = t_{\text{USRAM_pt}} + t_{\text{USRAM_auth}} + 0.01$$

2.3.5 How To Set Up Design and Memory Initialization

This section describes how to initialize PCIe, transceivers, and fabric RAM blocks using the **Configure Design Initialization Data and Memories** option in Libero SoC. Design and Memory Initialization is divided into three stages of initialization as shown in the following figure.

Figure 2-9. Design and Memory Initialization



1. The first stage client is responsible for bring-up of FPGA fabric and related IOs, and then de-asserts the FABRIC_POR_N signal. This client is stored in the sNVM at the top of the address space.
2. The second stage client initializes the PCIe and XCVR blocks present in the design. The client is stored in the sNVM and the starting address of the client is configurable.
3. The third stage client initializes the fabric RAMs present in the design. Each logical RAM in the design can be initialized from a different Storage Type—sNVM, uPROM, or SPI Flash. The starting address of these storage types is configurable.

Note: The second stage client initializes the PCIe and XCVR blocks present in the design. Import a text file to change the default PCIe/XCVR register values (custom configuration). This will modify the Stage 2 generated assembly file (from default flow). The format in the text file to change the register content is as follows:

Instance_Name, Register:Field_Name, and Hex value separated by spaces. For example:

PF_PCIE_0/PCIESS_LANE0_Pipe_AXI0_SER_DRV_CTRL:TXDRVTRIM 0xFFFFFFFF

Note: When initializing the RAM from SPI Flash, ensure that the System Controller SPI interface is in the Master mode by setting the IO_CFG_INTF pin to 1.

Note: The SPI Clock divider value specifies the required SPI SCK frequency to read the initialization data from SPI Flash. The SPI Clock divider value must be selected based on the external SPI Flash operating frequency range.

Table 2-3. SPI Clock Divider Value

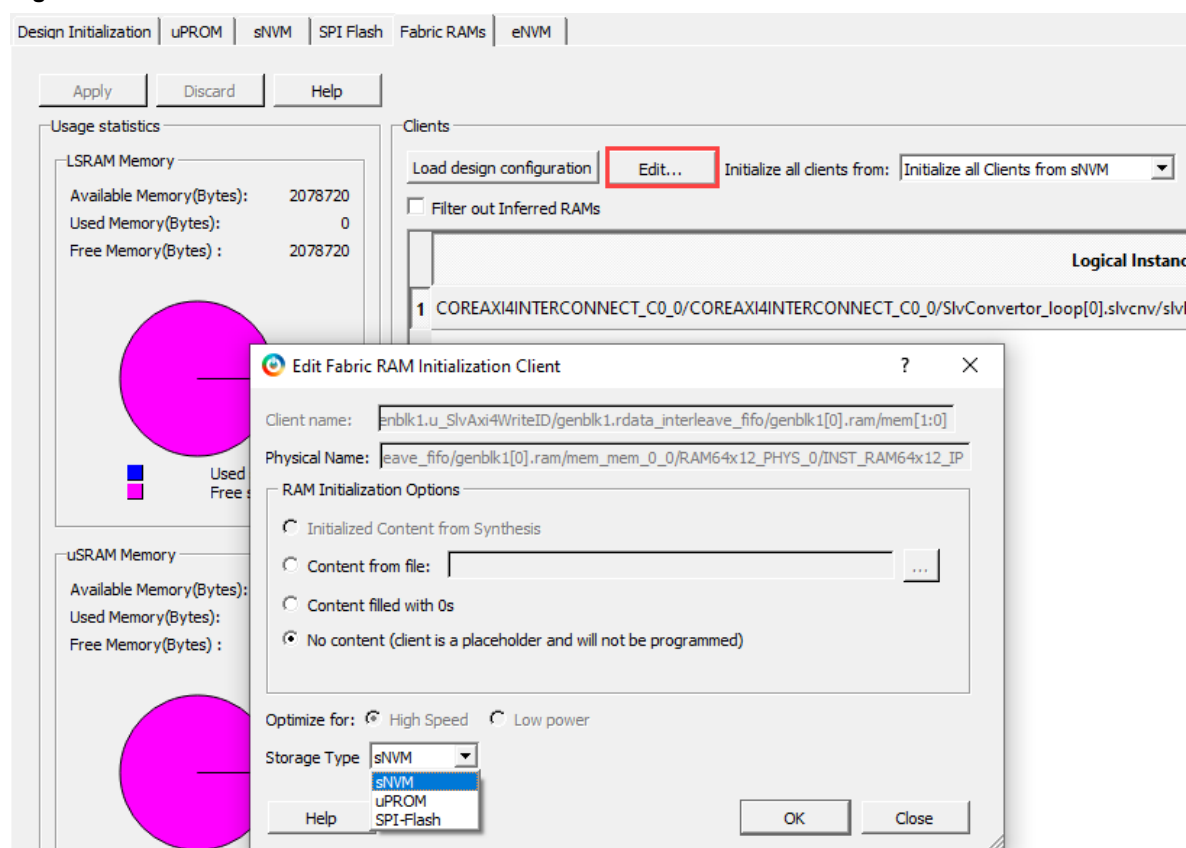
SPI Clock Divider Value	SCK Frequency
1	80 MHz
2	40 MHz
4	20 MHz
6	13.3 MHz

Follow these steps to initialize fabric RAMs at power-up:

1. Select the required logical RAM from the **Fabric RAMs** tab and click **Edit**. The Edit Fabric RAM Initialization Client window provides the following options to:
 - Initialize the client from an Intel-Hex (*.hex), Simple-Hex(*.shx), Motorola-S (*.s), or Microchip Binary (*.mem)

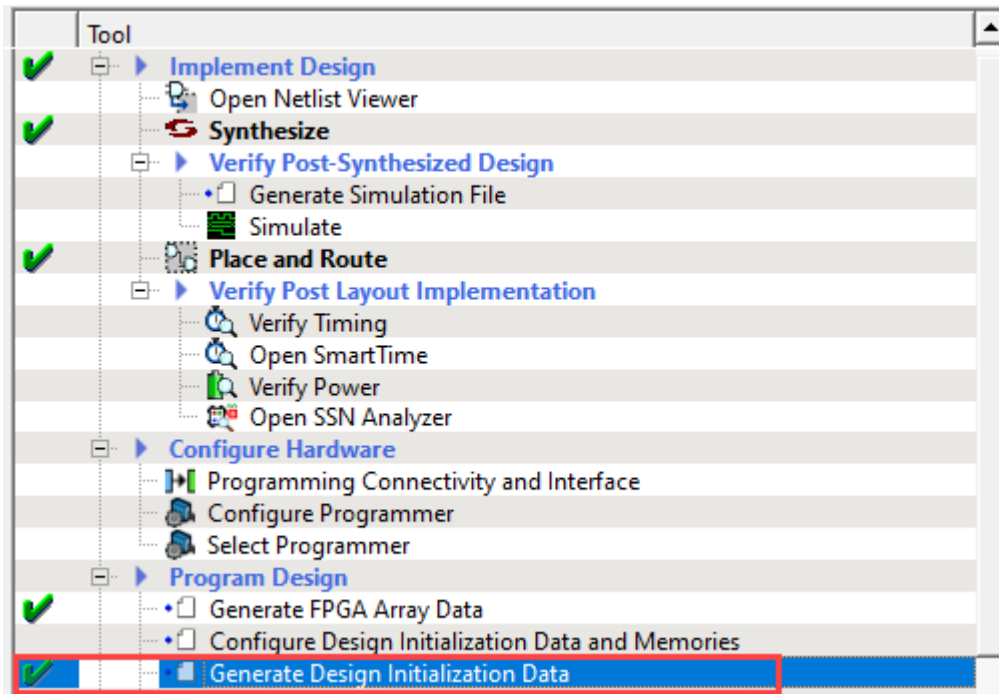
- Initialize the client with Zeros
- Create the client as a placeholder with no content
- Select **Storage Type** for the client

Figure 2-10. Fabric RAMs



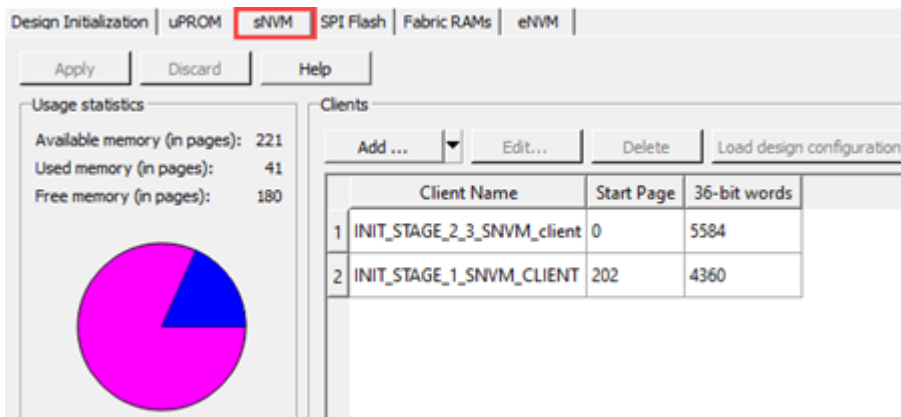
2. After configuring the RAM initialization client, click **Apply** on the **Fabric RAMs** tab.
3. Select **Generate Design Initialization Data** under **Design Flow** tab. It automatically generates the first, second, and third stage initialization clients, which are automatically added to the non-volatile memory that the user chooses.
The **Generate Design Initialization Data** is highlighted as shown in the following figure.

Figure 2-11. Generate Design Initialization Data



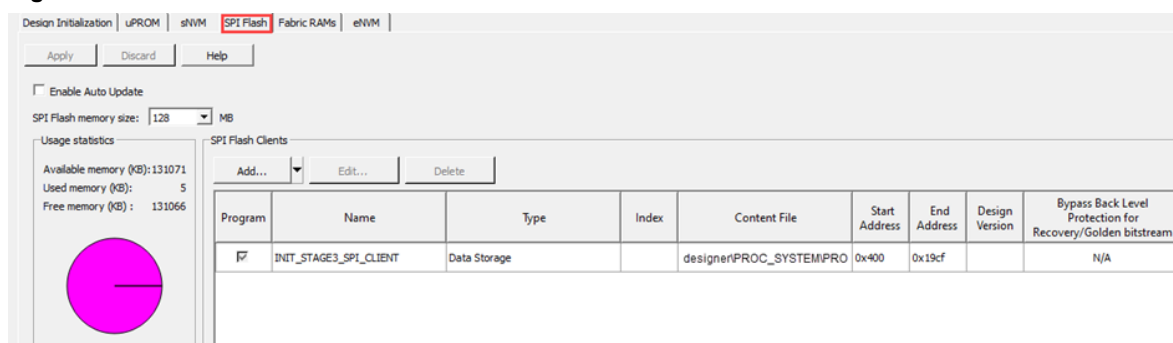
The initialization clients are added to the respective tab—μPROM, SNVM, SPI Flash, or eNVM (for PolarFire SoC FPGA only)—as shown in the following figure.

Figure 2-12. Initialization Clients Generated in sNVM



Note: The second stage client is added to sNVM if the user design includes the PCIe or XCVR block.

If SPI Flash is selected as the storage type, the initialization client is added to the **SPI Flash** tab as shown in the following figure.

Figure 2-13. Third Initialization Client on SPI Flash

4. If an external SPI Flash is chosen for stage 3, before completing the **Run PROGRAM Action**, you should generate **Generate SPI Flash Image** and **Run PROGRAM_SPI_IMAGE Action** from the **Design Flow** tab, as shown in the following figure.

Figure 2-14. Program SPI Flash Image

These steps ensure that PCIe, XCVR, and Fabric RAMs present in the design are initialized during power-up using initialization clients placed in the non-volatile memory based on the user selection.

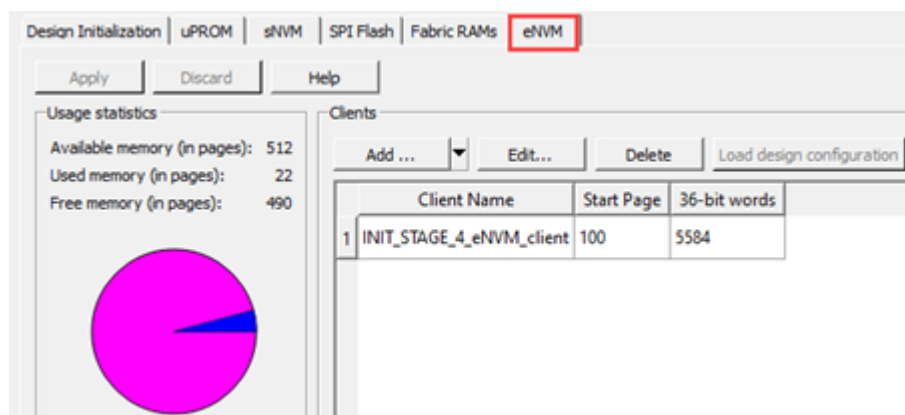
2.3.5.1 SPI Flash Client Configuration

Memory initialization data stored in SPI Flash can be encrypted and bound with the device. The Design Initialization tab provides the following encryption/binding options:

- SPI Flash – Binding Encrypted with Default Key
In this case, KLK is used as the root key for authentication and encryption/decryption
- SPI Flash – Binding Encrypted with User Encryption Key 1 (UEK1)
In this case, UEK1 is used as the root key for authentication and encryption/decryption
- SPI Flash – Binding Encrypted with User Encryption Key 2 (UEK2)
In this case, UEK2 is used as the root key for authentication and encryption/decryption

2.3.5.2 eNVM Client Configuration (For PolarFire SoC FPGA Only)

If eNVM is selected as the storage type, the initialization client is added to the eNVM tab as shown in the following figure. Once the initialization client is added to the eNVM, double-click **Generate Bitstream** from the **Design Flow** tab.

Figure 2-15. Fourth Stage Initialization Client in eNVM

2.3.6 Power-up To Functional (PUFT) Timing Data Report

The information about PUFT timing data is available in the Design Initialization Data and Memories report of the Libero SoC. To indicate the completion of initialization of each block, such as PCIE, XCVR, RAMs, a signal is asserted as part of device initialization after power-up (this is done as part of UIC). For example, PCIE_INIT_DONE signal is asserted after all the PCIE related registers are configured. The last signal that is asserted is DEVICE_INIT_DONE.

In cases of PCIE and XCVR blocks, the number of instructions used to initialize the registers of that block are counted after FABRIC_POR is asserted in each case. Software implementation of PUF timing for any signal is a product of 'number of instructions' and a constant (average time taken for one UIC instruction). This number is added to the report for every signal.

$$\text{PUFT}_{\text{signal}} = (\text{Number_Of_Instructions} \times \text{Constant}) \text{ ns}$$

This constant is based on the run time (of UIC script) data collected. Based on the number of instructions in that design and the amount of time taken by UIC, the average time taken for one UIC instruction is calculated.

In case of SRAM and μ SRAM blocks, the amount of time taken to initialize vary from number of blocks measured on a device. This average time to initialize one block is used to compute the PUF timing of that signal. There is a constant time taken by system controller to copy the data to initialize the first block (Constant_Copy_Time). When the first block is being initialized, the data for initializing the second block is copied in background.

$$\text{PUFT}_{\text{signal}} = \text{Constant_Copy_Time} + (\text{Number_Of_Blocks} \times \text{Average_Time_to_Init_One_Block}) \text{ ns}$$

These signals are asserted in a sequence so the PUFT timing for each signal depends on:

- The previous block(s) in the sequence being instantiated in the user design (or not)
- The configuration of the block (Some configurations may need a few additional registers.)

SRAMs and μ SRAMs can be initialized from different storage locations (sNVM, UPRAM, and SPI). In the case of SPI, additional data needs to be collected depending on the SPI clock divider value and the encryption type selected.

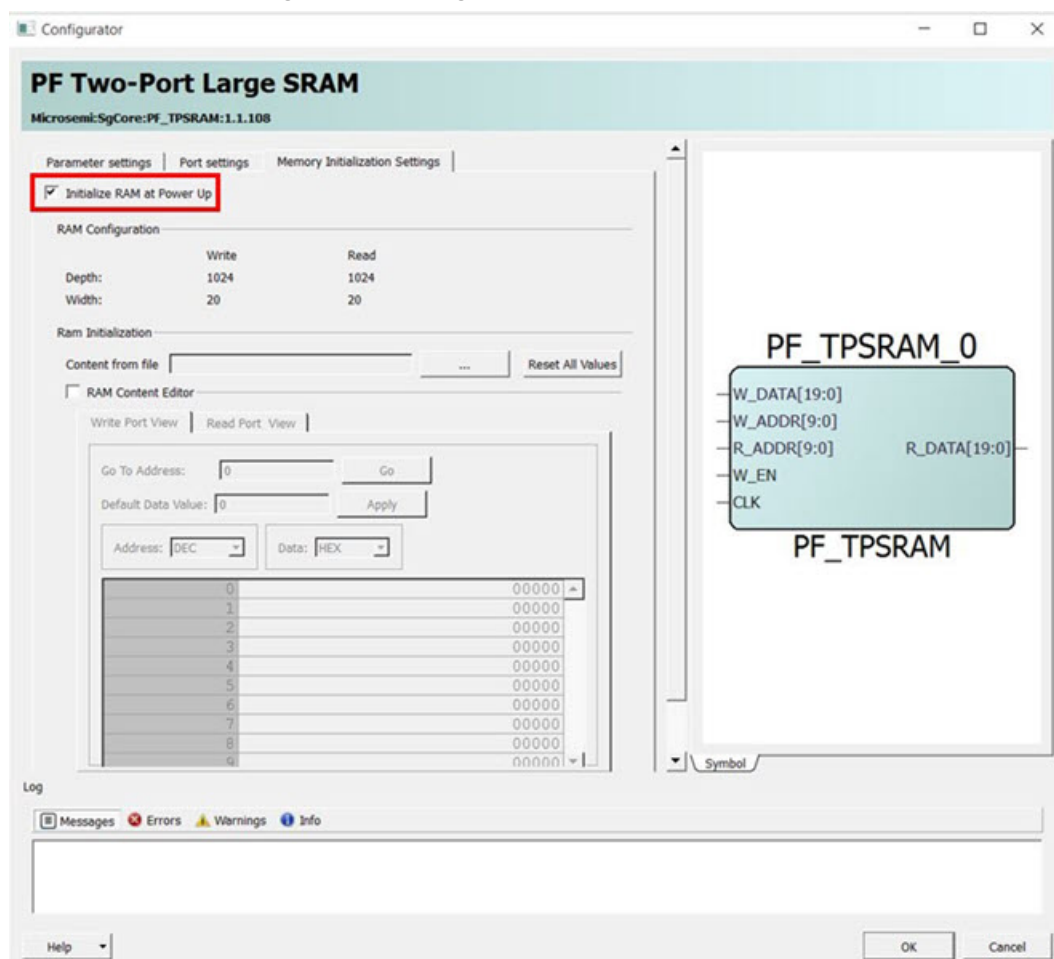
2.3.7 RAM Initialization Before Place and Route

During Fabric RAM IP core creation, the content file can be imported for simulation. The path of the content file is stored and passed to the Design and Memory Initialization stage.

Follow these steps to initialize Fabric RAM using LSRAM and μ SRAM configurator:

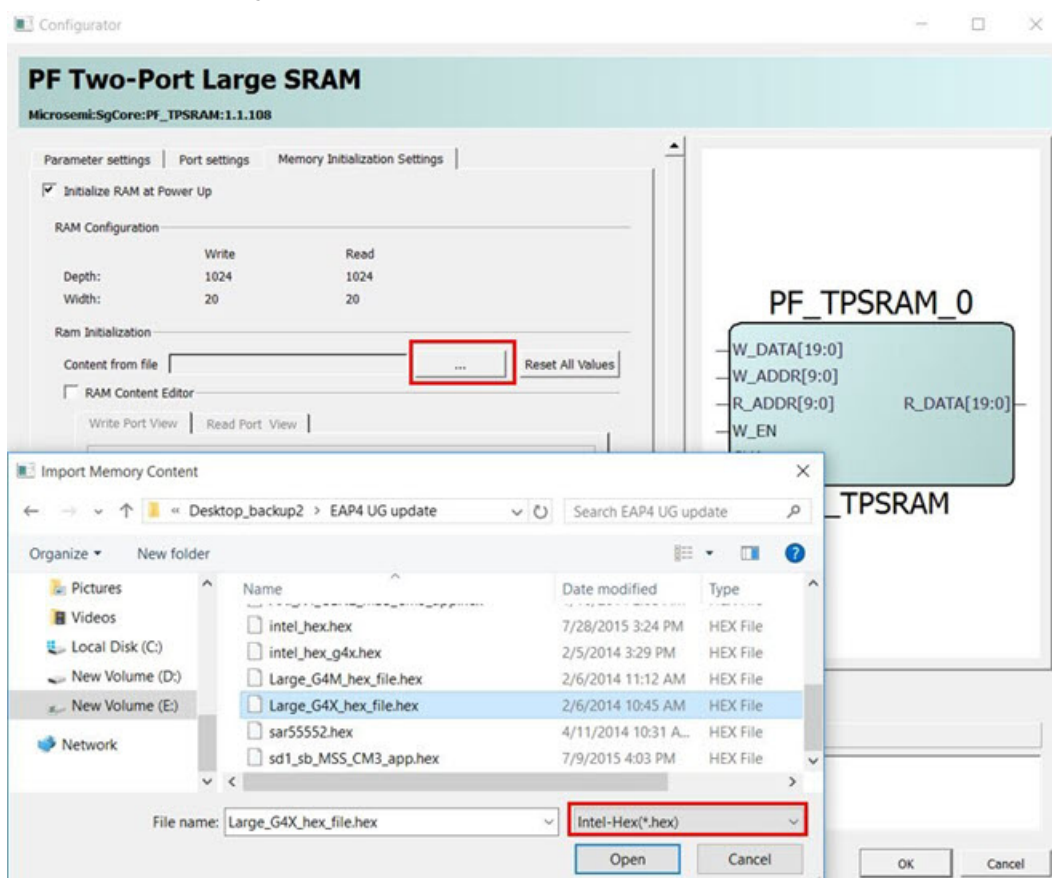
1. In the **PF Two-Port Large SRAM Configurator** window, select the **Memory Initialization Settings** tab. Then, select the **Initialize RAM at Power-up** check box as shown in the following figure.

Figure 2-16. PF Two-Port Large SRAM Configurator Window



2. Select the **Import File** option and import memory content file (Intel-Hex) from the **Import Memory Content** dialog box, as shown in the following figure. File extensions are set to *.hex for **Intel-Hex** files during import. The imported memory content is displayed in the **RAM Content Editor** pane.

Figure 2-17. Import Memory Content



3. After Place and Route, select the storage type for the content file and generate the initialization client using the procedure mentioned in [2.3.5 How To Set Up Design and Memory Initialization](#).

For more information about LSRAM and μ SRAM Configurators and user options, see the “**Embedded Memory Blocks**” section in [PolarFire FPGA and PolarFire SoC FPGA Fabric User Guide](#).

2.4 MSS Pre-Boot (For PolarFire SoC FPGA Only)

Upon successful completion of Design Initialization, MSS Pre-boot starts its execution. The MSS is released from a reset after completion of all normal startup procedures. The System Controller manages the programming, initialization, and configuration of the devices. For ES devices, MSS Pre-boot does not occur if the programmed device is configured for System Controller suspend mode.

The MSS pre-boot phase of initialization is coordinated by System Controller firmware, although it may make use of the E51 in the MSS Core Complex to perform certain parts of the pre-boot sequence.

The following events occur during the MSS pre-boot stage:

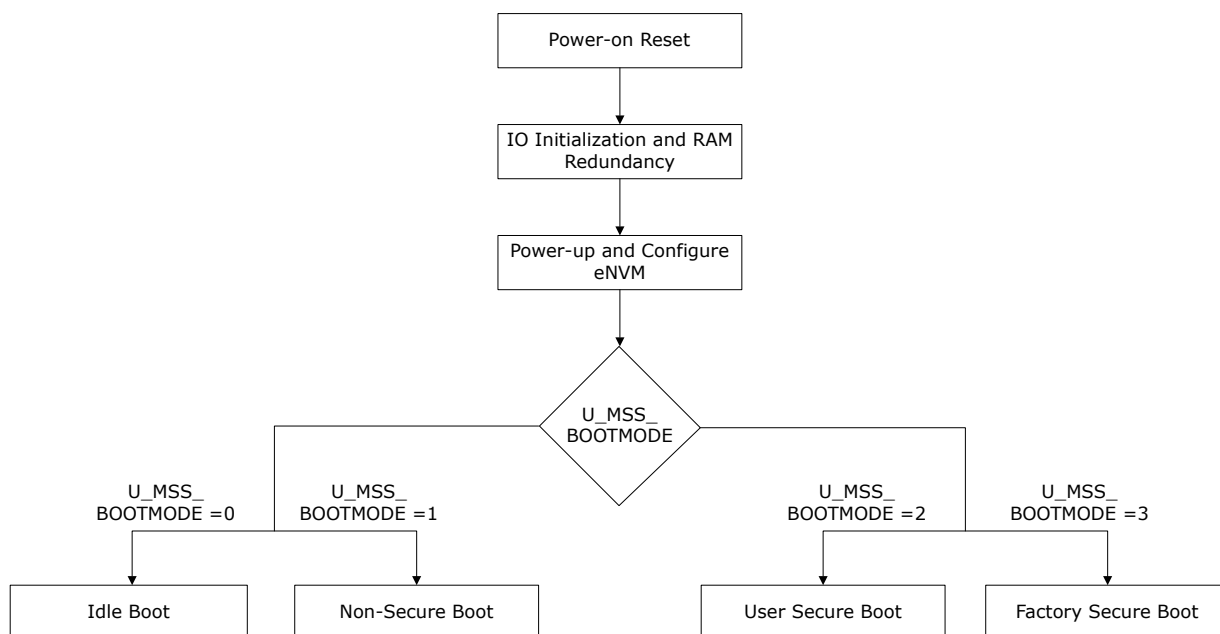
- Power-up of the MSS embedded Non-Volatile Memory (eNVM)
- Initialization of the redundancy repair associated with the MSS Core Complex L2 cache
- Authentication of User boot code (if User Secure boot option is enabled)
- Handover operational MSS to User Boot code

The MSS Core Complex can be booted in one of four modes. The following table lists the MSS pre-boot options, which can be configured and programmed into the sNVM. The boot mode is defined by the user parameter `U_MSS_BOOTMODE[1:0]`. Additional boot configuration data is mode-dependent and is defined by the user parameter `U_MSS_BOOTCFG` (see [Table 2-6](#) and [Table 2-8](#)).

Table 2-4. MSS Core Complex Boot Modes

U_MSS_BOOTMODE[1:0]	Mode	Description
0	Idle boot	MSS Core Complex boots from boot ROM if MSS is not configured
1	Non-secure boot	MSS Core Complex boots directly from address defined by the U_MSS_BOOTADDR
2	User secure boot	MSS Core Complex boots from sNVM
3	Factory secure boot	MSS Core Complex boots using the factory secure boot protocol

The boot option is selected as part of the Libero design flow. Changing the mode can only be achieved through the generation of a new FPGA programming file.

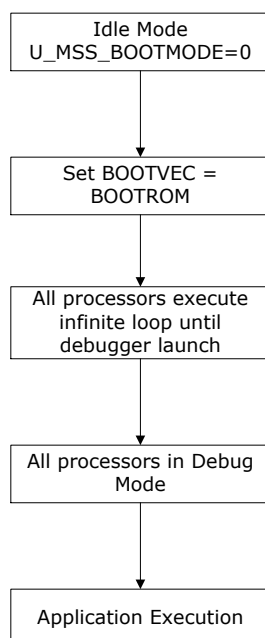
Figure 2-18. MSS Pre-boot Flow

2.4.1 Idle Boot

If the MSS is not configured (For example, blank device), then the MSS Core Complex executes a boot ROM program which holds all the processors in an infinite loop until a debugger connects to the target. The boot vector registers maintain their value until the device is reset or a new boot mode configuration is programmed. For configured devices, this mode can be implemented using the U_MSS_BOOTMODE=0 boot option in the Libero configurator.

Note: In this mode, U_MSS_BOOTCFG is not used.

The following figure shows the Idle boot flow.

Figure 2-19. Idle Boot Flow

2.4.2 Non-Secure Boot

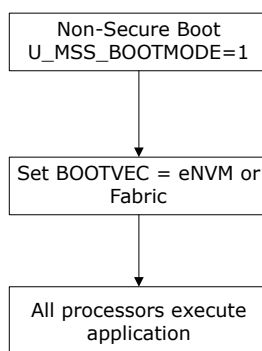
In this mode, the MSS Core Complex executes from a specified eNVM address without authentication. It provides the fastest boot option, but there is no authentication of the code image. The address can be specified by setting U_MSS_BOOTADDR in the Libero Configurator. This mode can also be used to boot from any FPGA fabric memory resource through FIC. This mode is implemented using the U_MSS_BOOTMODE=1 boot option.

The MSS Core Complex is released from reset with boot vectors defined by U_MSS_BOOTCFG (as listed in the following table).

Table 2-5. U_MSS_BOOTCFG Usage in Non-Secure Boot Mode 1

Offset (bytes)	Size (bytes)	Name	Description
0	4	BOOTVEC0	Boot vector for E51
4	4	BOOTVEC1	Boot vector for U540
8	4	BOOTVEC2	Boot vector for U541
16	4	BOOTVEC3	Boot vector for U542
20	4	BOOTVEC4	Boot vector for U543

The following figure shows the Non-Secure boot flow.

Figure 2-20. Non-Secure Boot Flow

2.4.3 User Secure Boot

This mode allows user to implement their own custom secure boot and the user secure boot code is placed in the sNVM. The sNVM is a 56 Kbytes non-volatile memory that can be protected by the built-in physically unclonable function (PUF). This boot method is considered secured because sNVM pages marked as ROM are immutable. On power up, the System Controller copies the user secure boot code from sNVM to Data Tightly Integrated Memory (DTIM) of the E51 Monitor core. E51 starts executing the user secure boot code.

If the size of the user secure boot code is more than the size of the DTIM then user needs to split the boot code into two stages. The sNVM may contain the next stage of the user boot sequence, which may perform authentication of the next boot stage using the user authentication/decryption algorithm.

If authenticated or encrypted pages are used, then the same USK key (that is, U_MSS_BOOT_SNVN_USK) must be used for all authenticated/encrypted pages.

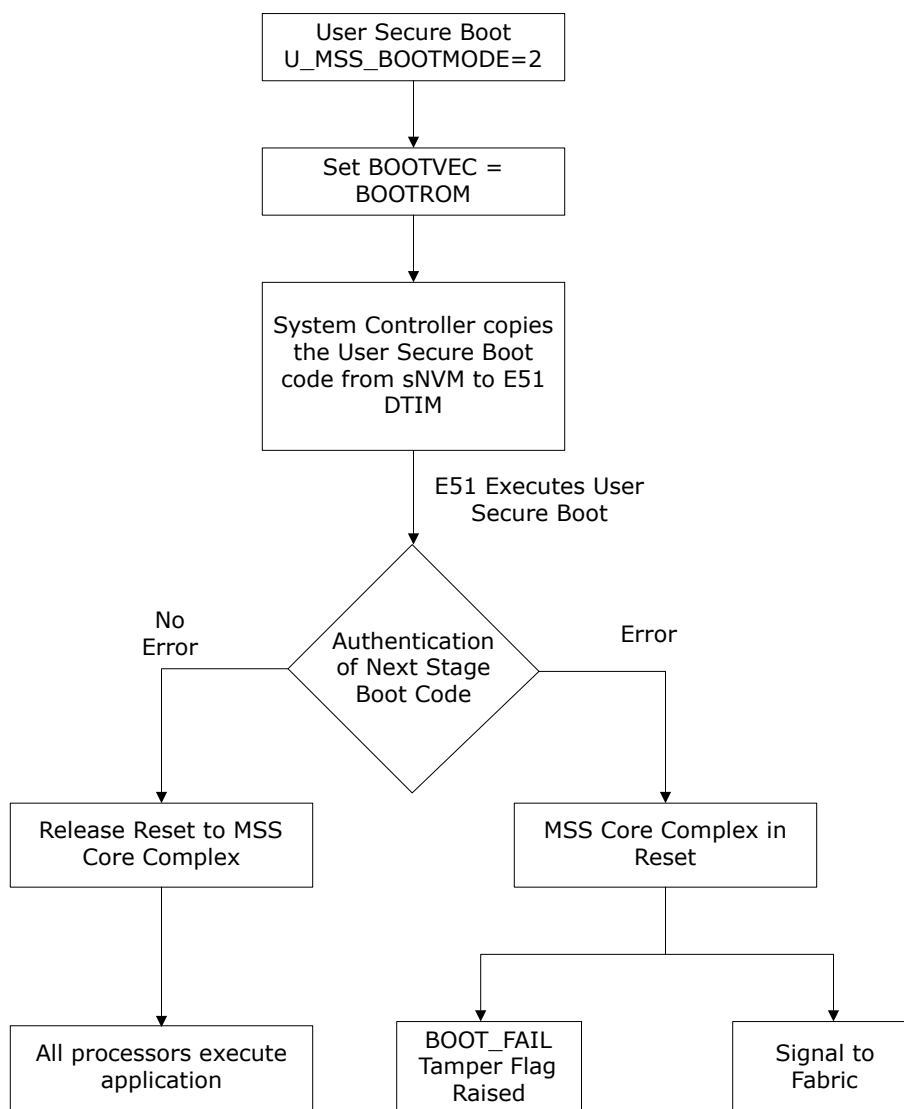
If authentication fails, the MSS Core Complex can be placed in reset and the BOOT_FAIL tamper flag can be raised. This mode is implemented using the U_MSS_BOOTMODE=2 boot option.

Table 2-6. U_MSS_BOOTCFG Usage in User Secure Boot

Offset (bytes)	Size (bytes)	Name	Description
0	1	U_MSS_BOOT_SNVN_PAGE	Start page in SNVM
1	3	RESERVED	For alignment
4	12	U_MSS_BOOT_SNVN_USK	For authenticated/encrypted pages

The following figure shows the user secure boot flow.

Figure 2-21. Factory Secure Boot



2.4.4 Factory Secure Boot

In this mode, the System Controller reads the Secure Boot Image Certificate (SBIC) from eNVM and validates the SBIC. On successful validation, System Controller copies the factory secure boot code from its private, secure memory area and loads it into the DTIM of the E51 Monitor core. The default secure boot performs a signature check on the eNVM image using SBIC which is stored in eNVM. If no errors are reported, reset is released to the MSS Core Complex. If errors are reported, the MSS Core Complex is placed in reset and the BOOT_FAIL tamper flag is raised. Then, the System Controller activates a tamper flag which asserts a signal to the FPGA fabric for user action. This mode is implemented using the U_MSS_BOOTMODE=3 boot option.

The SBIC contains the address, size, hash, and Elliptic Curve Digital Signature Algorithm (ECDSA) signature of the protected binary blob. ECDSA offers a variant of the DSA, which uses elliptic curve cryptography. It also contains the reset vector for each Hardware thread/core/processor core (Hart) in the system.

Table 2-7. Secure Boot Image Certificate (SBIC)

Offset	Size (bytes)	Value	Description
0	4	IMAGEADDR	Address of UBL in MSS memory map

.....continued

Offset	Size (bytes)	Value	Description
4	4	IMAGELEN	Size of UBL in bytes
8	4	BOOTVEC0	Boot vector in UBL for E51
12	4	BOOTVEC1	Boot vector in UBL for U540
16	4	BOOTVEC2	Boot vector in UBL for U541
20	4	BOOTVEC3	Boot vector in UBL for U542
24	4	BOOTVEC4	Boot vector in UBL for U543
28	1	OPTIONS[7:0]	SBIC options
28	3	RESERVED	—
32	8	VERSION	SBIC/Image version
40	16	DSN	Optional DSN binding
56	48	H	UBL image SHA-384 hash
104	104	CODESIG	DER-encoded ECDSA signature
Total	208	Bytes	—

DSN

If the DSN field is non-zero, it is compared against the device's own serial number. If the comparison fails, then the boot_fail tamper flag is set and authentication is aborted.

VERSION

If SBIC revocation is enabled by U_MSS_REVOCATION_ENABLE, the SBIC is rejected unless the value of VERSION is greater than or equal to the revocation threshold.

SBIC REVOCATION OPTION

If SBIC revocation is enabled by U_MSS_REVOCATION_ENABLE and OPTIONS[0] is '1', all the SBIC versions less than VERSION are revoked upon complete authentication of the SBIC. The revocation threshold remains at the new value until it increments again by a future SBIC with OPTIONS[0] = '1' and a higher VERSION field. The revocation threshold may only be incremented using this mechanism and can only be reset by a bit-stream.

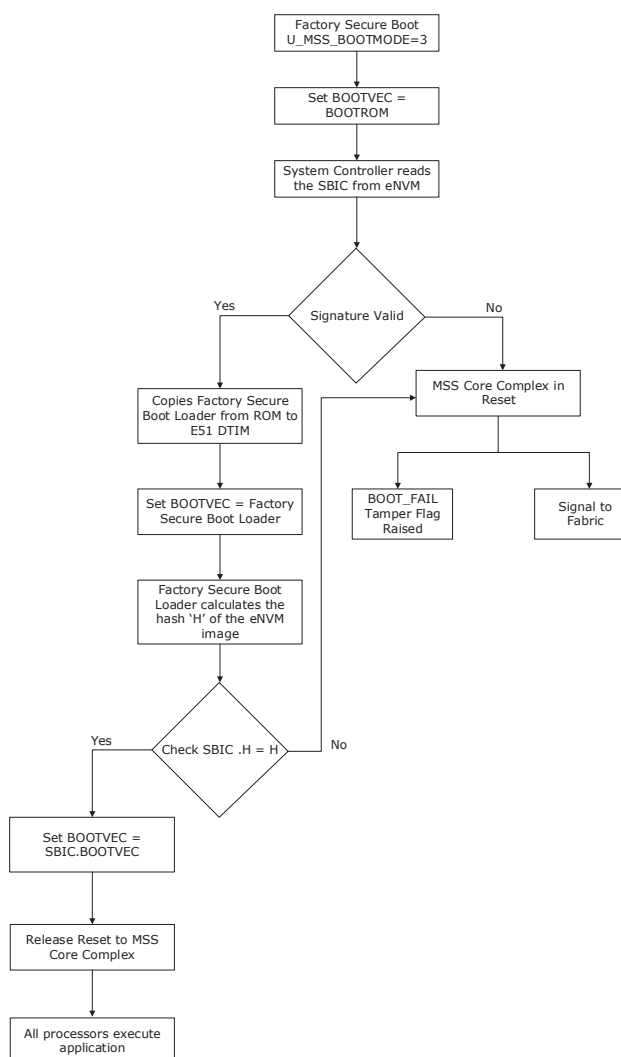
When the revocation threshold is updated dynamically, the threshold is stored using the redundant storage scheme used for passcodes such that a power failure during device boot does not cause a subsequent device boot to fail. If the update of revocation threshold fails, it is guaranteed that the threshold value is either the new value or the previous one.

Table 2-8. U_MSS_BOOTCFG Usage in Factory Boot Loader Mode

Offset (bytes)	Size (bytes)	Name	Description
0	4	U_MSS_SBIC_ADDR	Address of SBIC in MSS address space
4	4	U_MSS_REVOCATION_ENABLE	Enable SBIC revocation if non-zero

The following figure shows the factory secure boot flow.

Figure 2-22. Factory Secure Boot Flow



2.5 MSS User Boot (For PolarFire SoC FPGA Only)

MSS user boot takes place when the control is given from System Controller to MSS Core Complex. Upon successful MSS pre-boot, System Controller releases the reset to the MSS Core Complex. MSS can be booted up in one of the following ways:

- Bare Metal Application
- Linux Application
- AMP Application

For more information about MSS booting, see [PolarFire SoC Software Development and Tool Flow User Guide](#).

2.6 HSIO/GPIO Bank Initialization

Unused GPIO and HSIO banks can be left powered down or powered up. During the device power-up, the used GPIO and HSIO banks are simultaneously powered up along with all the other power supplies. All of the banks are initialized automatically with Flash configuration bits when fabric is powered up. All of the powered-up user IOs (HSIO/GPIO) go through an initial PVT calibration on power-up.

The time at which IOs are functional depends on a combination of the following:

- Device boot
- Ramp-up time of the power applied to the IO banks
- Calibration time of IOs (For example, DDR interfaces)

For low-speed operations below 100 MHz, IOs are functional after the power applied to IO banks exceeds the threshold levels. When GPIO is mapped to the OUTPUT PAD signals, the drive strength is weakened when initial calibration is complete. This occurs because the initial pre-calibrated drive strength is at maximum calibration code until IO calibration status/AUTOCALIB_DONE signal is asserted. It is recommended to monitor the IO calibration status/AUTOCALIB_DONE signal for both high-speed and low-speed signals because of the drive strength change.

If the user requires the IOs to be usable immediately upon completion of device boot, the IO power ramp time must be sufficiently short. The user can also apply slow or delayed IO power ramp times on IO banks to delay the time until which the IOs are usable. If the user is applying slow ramp rates to IO banks power supplies, the user logic in the fabric must monitor the state of the IO banks to know when they are usable as low-speed IOs.

Figure 2-23. Ramp-up Time

I/O Bank Settings

Bank

Choose Bank: **Bank2 - GPIO** ☐ Locked

Attributes

☒ Auto Calibration

Auto Calibration Ramp Time (ms) **50**

Voltage Selection

	Range	Min	Typical	Max
VDDI: Unassigned		N/A	N/A	N/A
VREF:				

☐ Use VREF default pins

How to handle placed macros incompatible with VDDI/VREF

☒ Unplace them

☐ Change I/O technology to be compatible

Available Technologies

Disabled Technologies

- BUSLVDSE25
- HCSL25
- HCSL33
- HSTL15I
- HSTL15II
- HSUL18I
- HSUL18II
- LCMDSE25

Help OK Cancel

The high-speed IO calibration process occurs automatically. The user's design in the FPGA fabric must monitor the completion of IO calibration or AUTOCALIB_DONE to use the IOs for high-speed applications. The status of

the IO calibration and bank power supply can be monitored using the status signals of the PolarFire/PolarFire SoC Initialization Monitor IP. The following figure shows Auto calibration timeout settings. Configure the Timeout option based on selected GPIO or HSIO in the user design.

Figure 2-24. Auto Calibration Timeout

Reports | StartPage | top.v | PF_IOD_GENERIC_TX_CO.v | Constraint Manager | Design and Memory Initialization | top

Design Initialization | uPROM | sNVM | SPI Flash | Fabric RAMs

Apply | Discard | Help

In design initialization, user design blocks such as LSRAM, uSRAM, transceivers, and PCIe can be initialized as an option using data stored in the non-volatile storage memory. The initialization data can be stored in uPROM, sNVM, or an external SPI Flash.

Follow the below steps to program the initialization data:

1. Set up your fabric RAMs initialization data, if any, using the 'Fabric RAMs' tab
2. Define the storage location of the initialization data
3. Generate the initialization clients
4. Generate or export the bitstream
5. Program the device

Design initialization specification

First stage (sNVM)

In the first stage, the initialization sequence de-asserts FABRIC_POR_IL.

Second stage (sNVM)

In the second stage, the initialization sequence initializes the PCIe and XCVR blocks present in the design.

Start address for second stage initialization client: 0x 00000000

Third stage (sNVM/uPROM/SPI-Flash)

In the third stage, the initialization sequence initializes the Fabric RAMs present in the design.

To save the initialization instructions in sNVM/uPROM/SPI-Flash, please use 'Fabric RAMs' tab to make your selection for each RAM client.

☐ Start address for sNVM clients: 0x 00000000

☐ Start address for uPROM clients: 0x 00000000

☐ Start address for SPI-Flash clients: 0x 00000400

SPI-Flash Binding: SPI-Flash - No-binding Plaintext SPI Clock divider value: 1(80 MHz)

☒ Broadcast instructions to initialize RAM's to zero's

Time Out (s): 128

Auto Calibration Time Out (ms): 3000

Custom configuration file: ...

Third stage initialization is not needed because RAM clients are not present.

The PolarFire/PolarFire SoC Initialization Monitor asserts BANK_#_CALIB_STATUS and BANK_#_VDDI_STATUS signals to the fabric. BANK_#_CALIB_STATUS can be used by the user logic to determine if the calibration completes for each IO bank. BANK_#_VDDI_STATUS signal can be used to monitor VDDI supply on specific IO banks.

The DRI clock (DRI_CLK) must be gated off until the assertion of DEVICE_INIT_DONE, which asserts at the end of the complete device initialization.

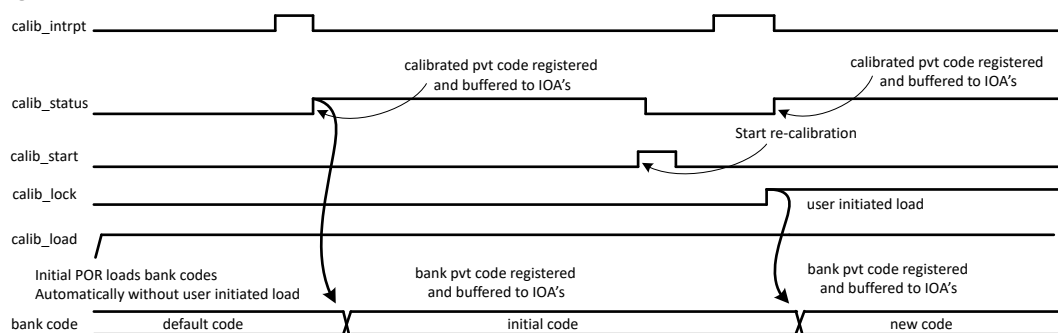
2.7 IO Recalibration

The PF_INIT_MONITOR IP and PFSOC_INIT_MONITOR IP are used to control the IO recalibration or to monitor the initial IO calibration. The following figure shows the recalibration operation.

When IO recalibration is enabled, the following ports are exposed in PFSOC_INIT_MONITOR IP:

- BANK_#_CALIB_STATUS
- BANK_#_CALIB_INTERRUPT
- BANK_#_CALIB_LOCK
- BANK_#_CALIB_LOAD
- BANK_#_CALIB_START

The following figure shows the recalibration operation.

Figure 2-25. Recalibration Operation

The following steps describe the recalibration operation:

1. Start a new calibration.
 - user activation of "bank#_calib_start"=1.
 - This initiates the calibration sequence.
2. The calibration engine indicates it has a new code.
 - Calibration engine activates the signal "bank#_calib_interrupt"=1.
 - At this point the new calibration code is ready, but has not been released to the IOs. It is being held ready for when the user requires it.
3. The user indicated that the engine should send out the new code to the IOs.
 - User activates the "bank#_calib_lock"=1.
 - This latches the new codes and distributes to the IOs.
4. The calibration engine indicates the latching of the new codes is complete.
 - Calibration engine activates the "bank#_calib_status"=1.
 - This indicates the calibration is complete to the user and IOs.

Note: bank#_calib_load must be tied high.

2.8 Transceiver Initialization

Transceiver power-up depends on VDDA, VDDA25, and VDD_XCVR_CLK.

VDD_XCVR_CLK is applicable if an external reference clock is used for transceivers. For a list of power supplies, see [5. Appendix: Power Supplies](#). During power-up, glitches can occur in the reference clocks and the data bits. The transceiver is initialized by the Flash configuration bits and the design initialization client, which is executed from the SNVM.

When XCVR_INIT_DONE/DEVICE_INIT_DONE signal from PFSOC_INIT_MONITOR goes high, the transceiver is completely configured. The user logic using the XCVR clock must be held in reset until the XCVR_INIT_DONE signal is asserted.

The transceiver data pins are in hot-plug mode at power-up. Programming bits can be used to detect TX and/or RX termination early to enable fast Receiver Detection in standards such as PCI Express.

The time taken to complete initialization of the transceiver subsystem depends on the number of lanes to be configured and the number of different high-speed serial protocols to be configured. When QUAD0 with 1 Lane is initialized with Libero default values, the XCVR initialization time is 282 μ s as listed in the following table. The worst case delay is calculated with all PCS and PMA register writes in stage 2 assembly file. For information about stage 2, see [Design and Memory Initialization](#).

Table 2-9. XCVR Initialization Time

Flow Type	No. of Register Writes in Stage 2 Assembly File	XCVR Initialization Time
Default Flow (No modification to generate files)	61	282 μ s

.....continued

Flow Type	No. of Register Writes in Stage 2 Assembly File	XCVR Initialization Time
Assembly File Modified Flow	136	594 μ s

2.9 User PLLs and DLLs Initialization

Both PLLs and DLLs are initialized automatically with Flash configuration bits when fabric is powered up.

2.10 PCIe Initialization

To achieve the PCIe initialization requirement, the physical layer is configured using Flash configuration bits. The remaining configuration is done during design initialization with the user data stored in the non-volatile memory.

For resetting the PCIESS, use the PCIe_x_PERST_N sideband reset input.

For resetting PCIESS using drivers, use hot reset (in-band reset). A hot reset is propagated in-band from one link neighbor to another by sending several TS1 (training sequence 1 packets) with bit0 of symbol 5 asserted. These TS1 are sent on all lanes. Once sent, the Tx and Rx of hot reset end up in detect link training state machine (LTSSM) state. Hot reset is initiated by setting the secondary bus reset bit in the root ports bridge control configuration register.

The time taken to complete initialization depends on the number of lanes to be configured and the number of PCI controllers to be configured. When PCIE0 controller is initialized with Libero default values, the PCIE initialization time is 440 μ s. When PCIE0 and PCIE1 are both enabled, the PCIE initialization time is 782 μ s.

The worst case PCIE initialization time is calculated with all PCIe Controller and Bridge register writes in stage 2 assembly file as listed in the following table.

Table 2-10. PCIe Initialization Time

PCIe Controller Selection	Default Flow (No Modification to Generated Files)		Assembly File Modified Flow	
	No. of Register Writes in Stage 2 Assembly File	PCIe Initialization Time	No. of Register Writes in Stage 2 Assembly File	PCIe Initialization Time
PCIE0-Enabled PCIE1-Disabled	99	440 μ s	388	937.5 μ s
PCIE0-Enabled PCIE1-Enabled	185	782 μ s	745	1759 μ s

For more information about PCIe initialization process, see [PolarFire FPGA and PolarFire SoC FPGA PCI Express User Guide](#).

2.11 State of Blocks During Power-Up

The following table shows the state of different blocks during device power-up.

Table 2-11. Default State During Device Power-Up

Block	POR	Device Boot	Design and Memory Initialization State
System Controller	Held in reset	Executing boot-up sequence	Performs design and memory initialization.

.....continued			
Block	POR	Device Boot	Design and Memory Initialization State
sNVM	Held in reset	Power up sequence, then functional	Functional
FPGA fabric array	Powered down	Power up sequence, then functional	Functional
LSRAM	Powered down	Powered up, uninitialized	Initialized with user data if configured.
μSRAM	Powered down	Powered up, uninitialized	Initialized with user data if configured.
μPROM	Powered down	Powered up	Functional
Math block	Powered down	Powered up	Functional
Transceiver and TX PLLs	Powered down	Powered up but not functional Termination Optionally Enabled	Initialized with user data and functional.
GPIO/HSIO - Low Speed (if power is applied)	Input buffers are disabled and output buffers are tri-stated. GPIO buffers are in hot-plug mode.	Powered up but not usable GPIO buffers are in hot-plug mode. HSIO buffers do not support hot-plug capability	Functional if IO and IO Auxiliary Supplies supply exceeds threshold.
GPIO/HSIO - High-speed (if power is applied)	Input buffers are disabled and output buffers are tri-stated GPIO buffers are in hot-plug mode.	Powered up but not usable GPIO buffers are in hot-plug mode. HSIO buffers do not support hot-plug capability.	Functional at high-speed after the completion of IO calibration if IO and IO Auxiliary Supplies are applied.
PCIe	Powered down	Powered up but not functional.	Initialized with user data and functional.
Transceiver IO	Tri-stated and hot-plug mode	Tri-stated in hot-plug mode Termination optionally enabled.	Termination Enabled, operational.
MSSIOs (for PolarFire SoC FPGA only)	Tri-stated	Tri-stated	Tri-stated
MSS (for PolarFire SoC FPGA only)	Powered down	Powered down	Powered down

Note: For more information about cold boot and warm boot power-up to functional time, see the “Power-Up to Functional Timing” section in respective [PolarFire FPGA Datasheet](#) or [PolarFire SoC FPGA Advance Datasheet](#).

3. PolarFire FPGA Resets

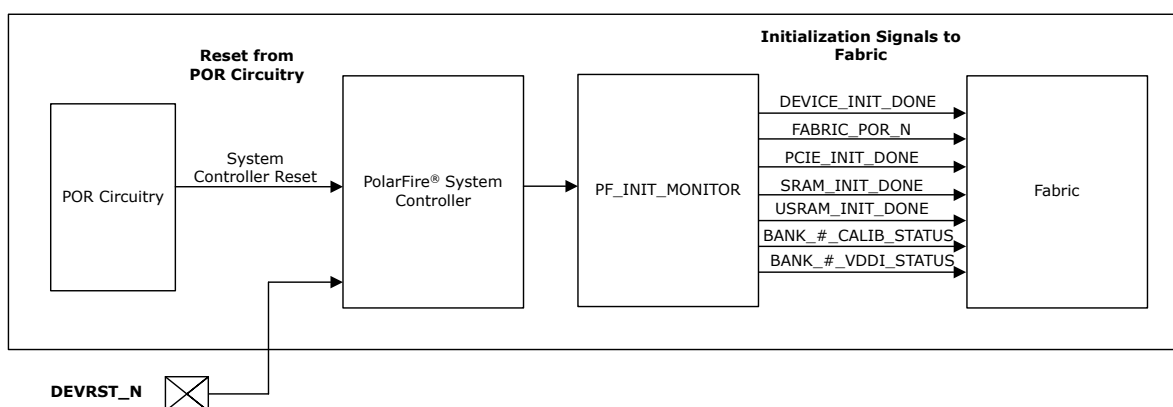
After a device power-up, the PolarFire FPGA system controller manages the device initialization. The following sections describe the PolarFire hard resets and user reset generation mechanism.

3.1 Hard Resets

PolarFire FPGA devices can be reset by any of the following sources:

- DEVRST_N pin
- Reset from POR circuitry

Figure 3-1. Simplified Block Diagram of Resets



3.1.1 Device Reset Pad (DEVRST_N)

DEVRST_N or device reset, is powered through the dedicated IO bank. The DEVRST_N assertion results in full re-initialization of the device, including the loading of user configuration data to PCIe, transceivers, and the re-initialization of MSS, fabric LSRAMs, and μ SRAMs.

For designing a robust system, users may use the dedicated DEVRST_N pin or a general purpose reset signal using any GPIO/HSIO as a global system reset. For the following cases, the users can use the DEVRST_N as a warm reset for the device:

- User design modifies auto-initialized fabric RAMs or PCIe configuration during operation.
- User design is using transceivers or UserCrypto.

In case of PCIe, for resetting the PCIeSS, use the PCIe_x_PERST_N input. The PCIe_x_PERST_N is a sideband reset input. For resetting PCIeSS using drivers, use hot reset (in-band reset).

A hot reset is propagated in-band from one link neighbor to another by sending several TS1 (training sequence 1 packets) with bit0 of symbol 5 asserted. These TS1 are sent on all the lanes. When sent, the Tx and Rx of hot reset end up in detect LTSSM (link training state machine) state. Hot reset is initiated by software by setting the secondary bus reset bit in the Root Port's Bridge control configuration register.

For all other use cases, it is recommended to use a general purpose reset signal using any GPIO, HSIO, or IO because they take much shorter time for design to come out of reset.

If the dedicated DEVRST_N is not used for warm resets, the DEVRST_N pin must be configured using one of the following methods:

- Drive the signal with a POR chip or an external device and keep the DEVRST_N asserted till the system/clocks are stable and the chip is properly powered up.
- Connect DEVRST_N to VDDI3 through a 1 k Ω ohm resistor per pin without sharing with any other pins.

- In this case, the user needs to ensure that all clocks going to the device are stable before the user design is released from power-on reset. The details of the minimum time taken for the fabric design to be activated after power-on is specified in the Power-Up To Functional Timing section of [PolarFire FPGA Datasheet](#).

Assertion of DEVRST_N or device reset initiated from the fabric (through PF_TAMPER macro) triggers the System Controller to power down the device in the following sequence:

1. The reset signal propagates as a non-maskable interrupt to the System Controller, which first disables all IOs.
2. The fabric gets powered down.
3. Resets are issued to all peripherals, such as transceivers, PCIe, PLLs, and DLLs.

3.1.2 Resets Initiated from POR Circuitry

POR circuitry releases the System Controller from the Reset state when all voltage supplies (VDD, VDD18, and VDD25) reach their stable minimum threshold levels. If any of the supplies fall below the minimum requirement, the device reset is issued.

3.2 User Reset Generation Scheme

The User Reset Generation Scheme are as follows:

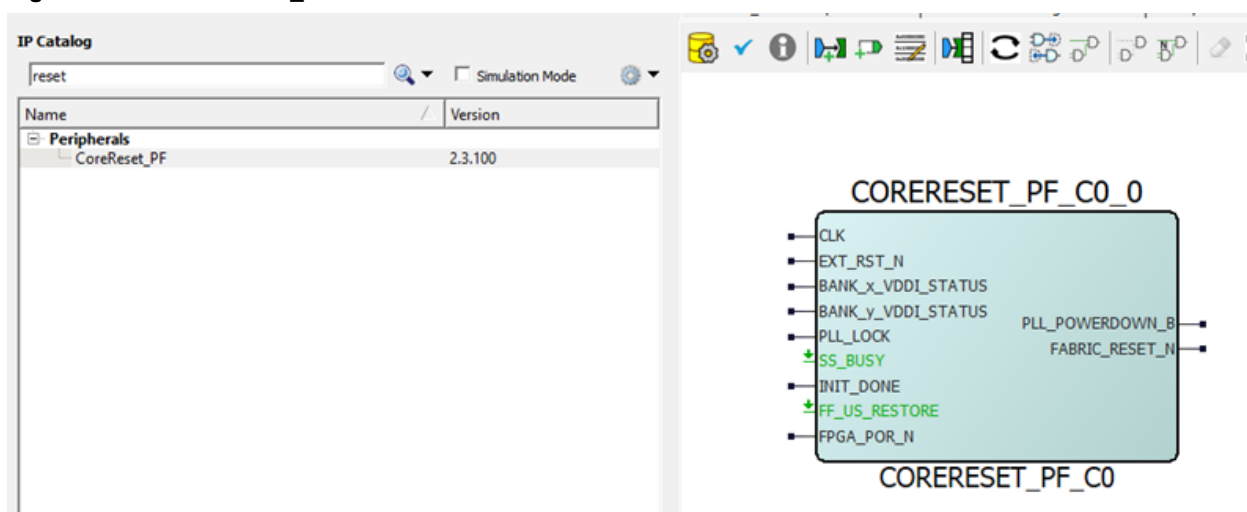
- If the design uses an external reset input, the reset input must be ignored until the input buffer of the reset signal is known to be operational. This is applicable for the following conditions:
 - FABRIC_POR_N negates
 - BANK_x_VDDI_STATUS asserts (where x is the number of the IO bank containing the input buffer)
- If the design uses a PLL with an external reference clock input, the PLL must be held in power-down state from the FPGA fabric until the input buffer of the external reference clock is known to be operational. This is when the later of the following two conditions occur:
 - FABRIC_POR_N negates
 - BANK_y_VDDI_STATUS asserts (where y is the number of the IO bank containing the input buffer)
- If the DRI_CLK is generated by a flip-flop in the FPGA fabric (e.g. a clock divider), this flip-flop must be asynchronously reset (e.g with FABRIC_POR_N).
- The flip-flop in the FPGA fabric that drives DRI_PSEL must be asynchronously reset (e.g with FABRIC_POR_N).
- A PLL lock signal should not be used directly as a reset signal if the PLL is configured not to emit clock pulses until after lock assertion because no clock edges occur during reset and any synchronous reset logic in the FGPA fabric is not correctly reset.

It is recommended to use CORERESET_PF as shown in [Figure 3-3](#) to incorporate these requirements.

The CORERESET_PF IP core is included in the Libero IP catalog as shown in [Figure 3-2](#). This IP core synchronously de-asserts the reset to the downstream logic in user-specified clock domain. As a result, the reset assertion is asynchronous but the negation is synchronous to the clock. This IP core ensures that the recovery time is met and that all of the flip-flops come out of reset in the same clock pulse.

The CORERESET_PF IP combines the resets from multiple sources like external GPIO, PLL lock, and PF_INIT_MONITOR blocks.

Figure 3-2. CORERESET_PF IP

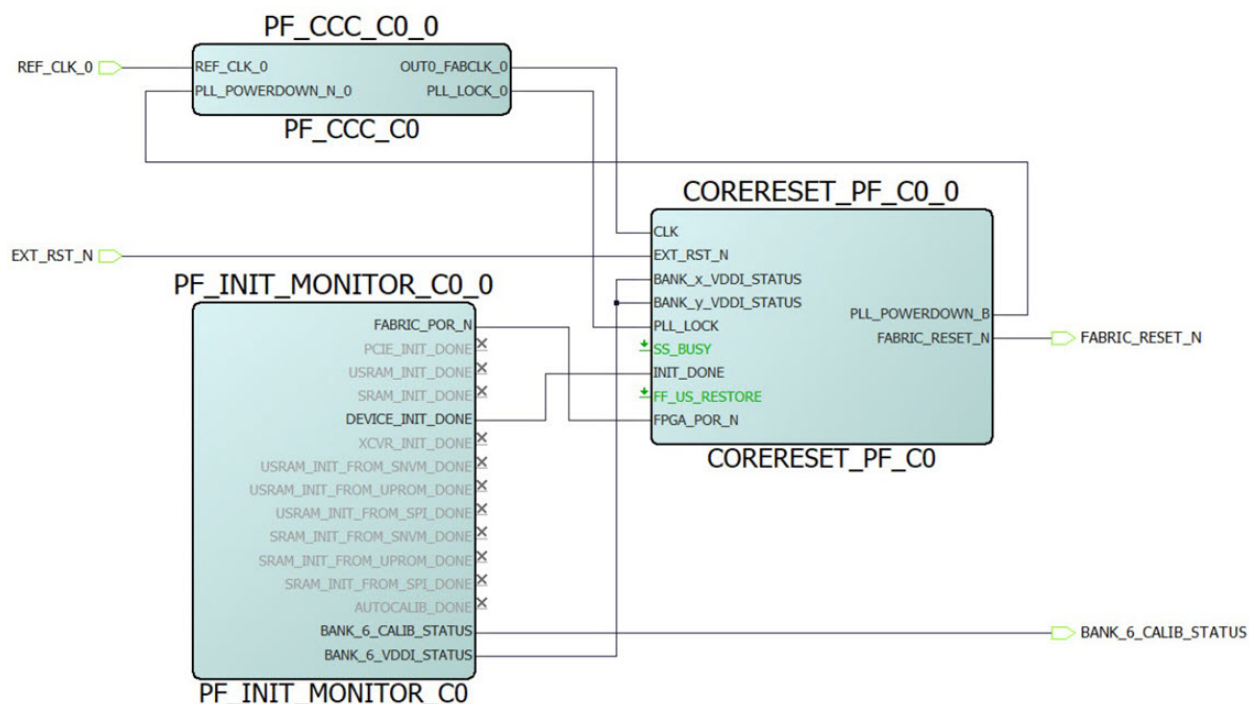


Note: For more information about the CORERESET_PF IP, see the CORERESET_PF handbook available in Libero catalog.

PolarFire Initialization Monitor (PF_INIT_MONITOR component) can be used for issuing reset to the user logic. The following figure shows an example use case of PF_INIT_MONITOR. In this example, the DEVICE_INIT_DONE signal is connected to the INIT_DONE signal of the RESET_GEN_0 block (CORERESET_PF IP) to give a synchronous reset signal to the user logic. The DEVICE_INIT_DONE signal gets asserted after the completion of device initialization.

In this example, EXT_RST_N and REF_CLK are connected to Bank 6. BANK_x_VDDI_STATUS and BANK_y_VDDI_STATUS are connected to Bank_6_VDDI_STATUS by enabling the Bank_6_VDDI_STATUS in PF_INIT_MONITOR IP. Bank6_CALIB_STATUS can be used for monitoring the GPIO calibration status, if any of the GPIO is connected to Bank6.

Figure 3-3. Example of PolarFire Initialization



4. PolarFire SoC FPGA Resets

The fabric flip-flops powers-up in an intermediate state. The reset logic should be included in the design for proper functioning. A reset pulse is required to force the initial state of flip-flops to a known value.

4.1 User Resets

4.1.1 Device Reset Pad (DEVRST_N)

DEVRST_N or device reset, is powered through the dedicated IO bank. The DEVRST_N assertion results in full re-initialization of the device, including the loading of user configuration data to PCIe, transceivers, and the re-initialization of MSS, fabric LSRAMs, and μ SRAMs.

For designing a robust system, users may use the dedicated DEVRST_N pin or a general purpose reset signal using any GPIO/HSIO as a global system reset. For the following cases, the users can use the DEVRST_N as a warm reset for the device:

- User design modifies auto-initialized fabric RAMs or PCIe configuration during operation.
- User design is using transceivers or UserCrypto.

In case of PCIe, for resetting the PCIeSS, use the PCIe_x_PERST_N input. The PCIe_x_PERST_N is a sideband reset input. For resetting PCIeSS using drivers, use hot reset (in-band reset).

A hot reset is propagated in-band from one link neighbor to another by sending several TS1 (training sequence 1 packets) with bit0 of symbol 5 asserted. These TS1 are sent on all the lanes. When sent, the Tx and Rx of hot reset end up in detect LTSSM (link training state machine) state. Hot reset is initiated by software by setting the secondary bus reset bit in the Root Port's Bridge control configuration register.

For all other use cases, it is recommended to use a general purpose reset signal using any GPIO, HSIO, or IO because they take much shorter time for design to come out of reset.

If the dedicated DEVRST_N is not used for warm resets, the DEVRST_N pin must be configured using one of the following methods:

- Drive the signal with a POR chip or an external device and keep the DEVRST_N asserted till the system/clocks are stable and the chip is properly powered up.
- Connect DEVRST_N to VDDI3 through a 1 k Ω ohm resistor per pin without sharing with any other pins.
 - In this case, the user needs to ensure that all clocks going to the device are stable before the user design is released from power-on reset. The details of the minimum time taken for the fabric design to be activated after power-on is specified in the Power-Up To Functional Timing section of [PolarFire SoC FPGA Advance Datasheet](#).

4.1.2 Device Reset from Fabric

The TR_RESET_DEVICE signal from the fabric may be pulsed high by user logic in order to initiate a full device reset and re-boot. This TR_RESET_DEVICE signal is one of the tamper response control signal. The TR_RESET_DEVICE signal can be used as a tamper response to a detected tamper event in the fabric. In this case, the signal should be pulsed low for a short duration. For information about pulse duration, see [PolarFire SoC FPGA Advance Datasheet](#).

Assertion of DEVRST_N or device reset initiated from the fabric triggers the System Controller to power down the device in the following sequence:

1. The reset signal propagates as a non-maskable interrupt to the System Controller, which first disables all IOs.
2. Starts the Watchdog timer to schedule an device reset
3. Powers down the fabric.

Resets are issued to all peripherals, such as MSS, fabric, transceivers, PCIe, PLLs, and DLLs. For information about peripherals, see [PolarFire SoC FPGA MSS Technical Reference Manual](#).

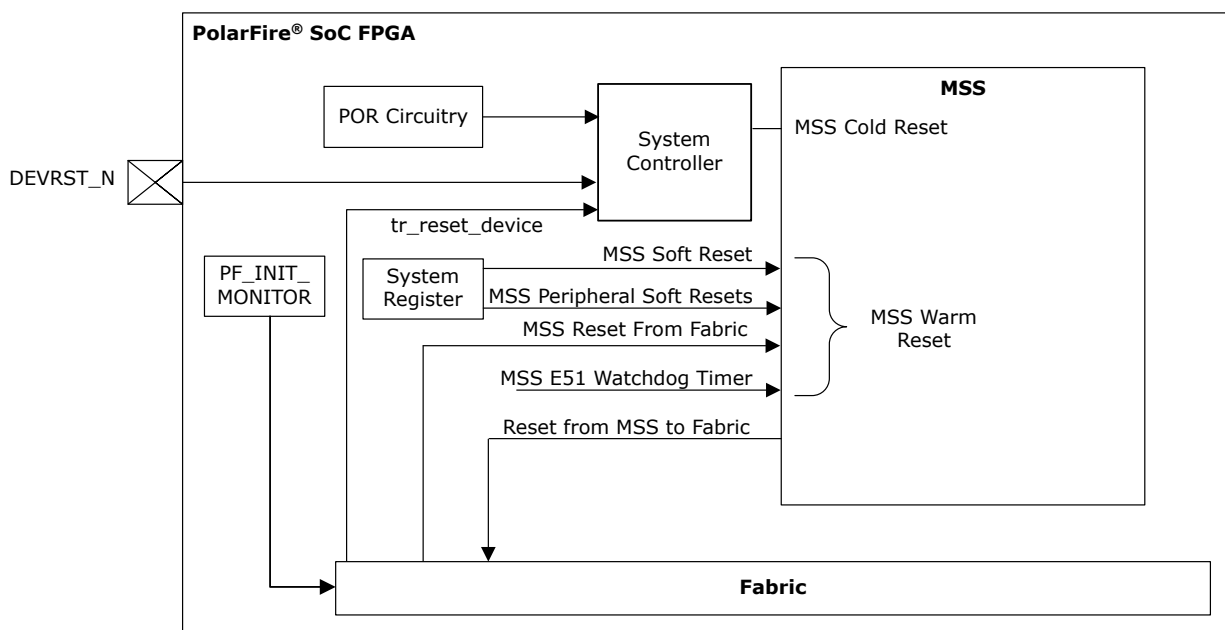
4.2 MSS Resets

After device power-up, the PolarFire SoC System Controller manages the device initialization. After the MSS warm reset, the firmware sequences the MSS back out of reset. Following are the PolarFire SoC resets:

- Microprocessor subsystem (MSS) Cold Reset
- MSS Warm Reset
- MSS Peripheral Soft Resets
- User Reset

For information about MSS, see [PolarFire SoC FPGA MSS Technical Reference Manual](#).

Figure 4-1. Block Diagram of MSS Resets



4.2.1 MSS Cold Reset

MSS cold reset is initiated by the Power on Reset (POR) circuitry when the device is powered on. MSS cold reset results in resetting of all the functionality within the MSS except the eNVM. eNVM can be reset using SOFT_RESET_CR register.

4.2.2 MSS Warm Reset

Any of the four MSS warm reset provides a method to reset the entire MSS and all the peripherals. This results in the asynchronous resetting of all functionality within the MSS (except the MSSIO configuration, IOMUXes and potentially MSS GPIO peripherals, if configured to be reset by fabric). The MSS internally remains in reset until the warm reset source is removed. When the warm reset signal is removed, an interrupt is generated to the System Controller, to indicate the MSS warm reset release event. After this, the System Controller firmware sequences the MSS back out of reset.

Following are the sources for initiating warm resets of the MSS.

4.2.2.1 MSS Soft Reset

An MSS_RESET_CR soft reset register can be written with a specific value via the application code in order to fully reset the MSS. The following table lists the MSS Soft Reset register names and their description.

Table 4-1. MSS_RESET_CR

	Register Name	Type	Default Value	Field Description
31:16	Reserved	RO	0x0000	Reserved
15:0	RESET_VALUE	RW	0x0000	When written, 16'hDEAD causes a full MSS reset. The reset clears this register. The register may be written to any value but only a value of 16'hDEAD causes the reset to happen.

4.2.2.2 MSS Reset from Fabric

User logic in the fabric asserts a reset signal to asynchronously reset the MSS.

4.2.2.3 MSS E51 Processor Watchdog Timeout Reset

The MSS can be configured such that the E51 processor's watchdog timer causes a reset of the MSS when the timer runs out.

MSS Reset Reasons

MSS can be reset in various ways as explained in the preceding sections. The user can access the 32-bit register RESET_SR to know which reset caused the MSS to be reset. The following table lists the reason for resetting the MSS.

Table 4-2. MSS Reset Reasons

Reason	Reset Reason Bit	Asserted By	Notes
SCB_PERIPH_RESET	0	SCB	This is the power on reset. This fully resets the MSS including eNVM trim values. Additional bits in the SOFT-RESET register also allow the SCB registers to be reset.
SCB_MSS_RESET	1	SCB, CPU, MSS	This resets the MSS including the Core Complex, Peripherals and all AXI infrastructure. It does not reset the eNVM trim values and SCB registers.
SCB_CPU_RESET	2	SCB, CPU, MSS	This resets the Core Complex only. This reset should be used in most cases as the MSS will require resetting at the same time to clear outstanding AXI transactions and so on.
DEBUGGER_RESET	3	Debugger	This is asserted by the Core Complex debugger and has the same effect as the SCB_MSS_RESET.
FABRIC_RESET	4	Fabric	This is asserted by the fabric and has the same effect as the SCB_MSS_RESET. This reset is disabled by a system register bit at reset and does not function until enabled.
WDOG_RESET	5	Watchdog	This indicates that the watchdog reset has been activated.
GPIO_RESET	6	Fabric	This indicates that the fabric GPIO reset was asserted. It resets the GPIO blocks if the GPIOs are configured to be reset by this signal. It does not reset the MSS.
SCB_BUS_RESET	7	Fabric	Indicates that SCB bus reset has occurred.

.....continued			
Reason	Reset Reason Bit	Asserted By	Notes
CPU_SOFT_RESET	8	CPU	Indicates that the CPU resets the MSS using the soft reset register.
Reserved	31:9		Reserved

4.2.2.4 MSS Peripheral Soft Resets

Each MSS peripheral has a soft reset register (SOFT_RESET_CR) bit associated with it in the MSS system registers and this bit must be written to “1” and then “0” to allow the peripheral to be used. When the MSS is reset, all these resets are asserted.

Table 4-3. MSS Peripheral Soft Resets

ADDR	Register	Field	Bit	Type	Reset value
x88	SOFT_RESET_CR	ENVM	0	RW	0x0

Following is the exception for MSS peripheral soft resets:

MSS GPIO Soft Reset: Each of the three MSS GPIO blocks can be configured to be reset by MSS warm reset or by the MSS GPIO reset signal from the fabric (if the device is programmed).

If configured to use the MSS warm reset (the default configuration), then they are also reset by MSS GPIO soft reset registers in the MSS system registers.

If configured to use the GPIO fabric reset, the MSS GPIO registers state are unaffected by writes to the MSS GPIO soft reset registers. However, these MSS GPIO registers are reset during the handling of the MSS warm reset event by the System Controller firmware.

4.2.3 MSS eNVM Reset

Reset of the eNVM is handled by the System Controller.

4.2.4 Resets from MSS to Fabric

There is a status signal from the MSS to the fabric, which indicates the reset status of MSS. This signal can be used by the fabric logic to hold the data transfers between MSS and fabric.

4.3 User Reset Generation Scheme

The User Reset Generation Scheme are as follows:

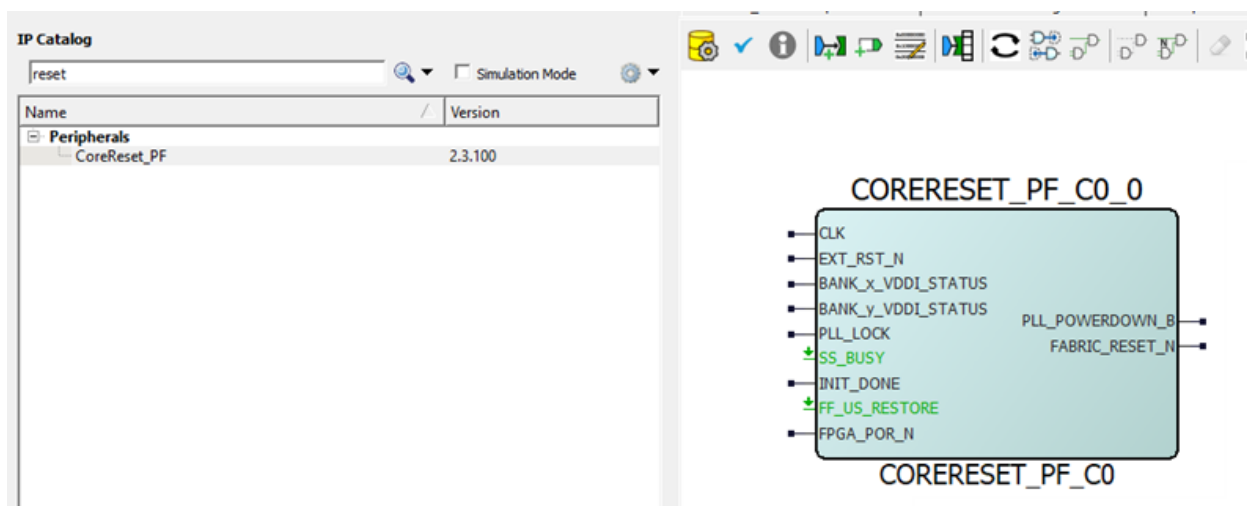
- If the design uses an external reset input, the reset input must be ignored until the input buffer of the reset signal is known to be operational. This is applicable for the following conditions:
 - FABRIC_POR_N negates
 - BANK_x_VDDI_STATUS asserts (where x is the number of the IO bank containing the input buffer)
- If the design uses a PLL with an external reference clock input, the PLL must be held in power-down state from the FPGA fabric until the input buffer of the external reference clock is known to be operational. This is when the later of the following two conditions occur:
 - FABRIC_POR_N negates
 - BANK_y_VDDI_STATUS asserts (where y is the number of the IO bank containing the input buffer)
- If the DRI_CLK is generated by a flip-flop in the FPGA fabric (e.g. a clock divider), this flip-flop must be asynchronously reset (e.g with FABRIC_POR_N).
- The flip-flop in the FPGA fabric that drives DRI_PSEL must be asynchronously reset (e.g with FABRIC_POR_N).
- A PLL lock signal should not be used directly as a reset signal if the PLL is configured not to emit clock pulses until after lock assertion because no clock edges occur during reset and any synchronous reset logic in the FGPA fabric is not correctly reset.

It is recommended to use CORERESET_PF as shown in [Figure 4-3](#) to incorporate these requirements.

The CORERESET_PF IP core is included in the Libero IP catalog as shown in [Figure 4-2](#). This IP core synchronously de-asserts the reset to the downstream logic in user-specified clock domain. As a result, the reset assertion is asynchronous but the negation is synchronous to the clock. This IP core ensures that the recovery time is met and that all of the flip-flops come out of reset in the same clock pulse.

The CORERESET_PF IP combines the resets from multiple sources like external GPIO, PLL lock, and PF_INIT_MONITOR blocks. The CORERESET_PF IP generates system-level synchronous reset (FABRIC_RESET_N) for MSS and fabric logic.

Figure 4-2. CORERESET_PF IP

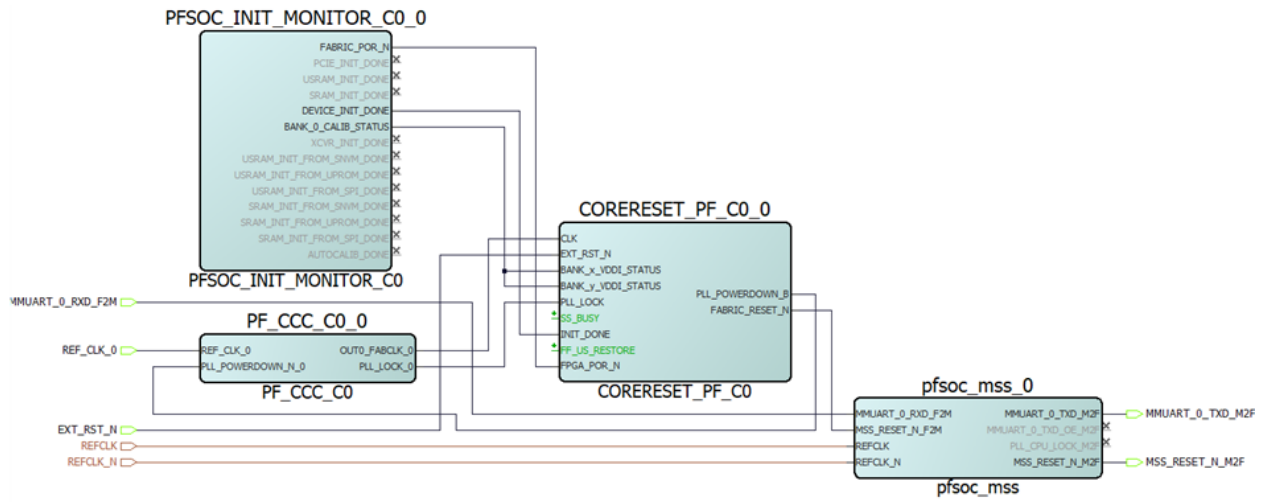


Note: For more information about the CORERESET_PF IP, see the CORERESET_PF handbook available in Libero catalog.

PolarFire SoC Initialization Monitor (PFSOC_INIT_MONITOR component) can be used for issuing reset to the user logic. The following figure shows an example use case of PFSOC_INIT_MONITOR and PFSOC_MSS_C0_0. In this example, the DEVICE_INIT_DONE signal is connected to the INIT_DONE signal of the RESET_GEN_0 block (CORERESET_PF IP) to give a synchronous reset signal to the user logic.

In this example, EXT_RST_N and REF_CLK are connected to Bank 0. BANK_x_VDDI_STATUS and BANK_y_VDDI_STATUS are connected to Bank_0_VDDI_STATUS by enabling the Bank_0_VDDI_STATUS in PFSOC_INIT_MONITOR IP. Bank0_CALIB_STATUS can be used for monitoring the GPIO calibration status, if any of the GPIO is connected to Bank0. The FABRIC_RESET_N signal of the PFSOC_MSS_C0_0 IP is connected to MSS_RESET_N_F2M of PFSOC_MSS_C0_0 and MSS_RESET_N_M2F is connected to other fabric related peripherals to give a synchronous reset signal to the user logic. The DEVICE_INIT_DONE signal gets asserted after the completion of design initialization.

Figure 4-3. Example of PolarFire SoC Initialization



5. Appendix: Power Supplies

The following table lists the power supplies.

Table 5-1. Power Supplies in PolarFire SoC Devices

Power Supply	Description
VDD	For fabric core and transceiver/PCIe blocks.
VDD18	For fabric programming and RC oscillators.
VDD25	For corner phase-locked loop (PLLs) and on-chip non-volatile memory (sNVM).
VDDIx	For IO banks.
VDDAUXx	For GPIO and HSIO banks.
VDDA	For transceiver.
VDDA25	For transceiver PLLs.
VDD_XCVR_CLK	For transceiver reference clock input buffers.

6. Revision History

The revision history table describes the changes that were implemented in the document. The changes are listed by revision, starting with the most current publication.

Revision	Date	Description
B	08/2021	<p>The following documents are merged in this revision:</p> <ul style="list-style-type: none"> • UG0725: PolarFire FPGA Device Power-up and Reset User Guide • PolarFire SoC FPGA Power-up and Reset User Guide
A	03/2021	<p>The following is a summary of the changes made in this revision.</p> <ul style="list-style-type: none"> • Information about the transceiver initialization time was added. See Transceiver Initialization. • Information about the PCIe initialization time was added. See PCIe Initialization. • Information about IO re-calibration was added. See IO Recalibration. • Document formatted to Microchip template. Document number is changed from 50200890 to DS60001676.
3.0	10/2020	<p>The following is a summary of the changes made in this revision.</p> <ul style="list-style-type: none"> • Information about ramp-up time was added. See 2.6 HSIO/GPIO Bank Initialization. • Information about low-speed IO calibration was added. See 2.6 HSIO/GPIO Bank Initialization. • Information about 2.4 MSS Pre-Boot (For PolarFire SoC FPGA Only) and 2.5 MSS User Boot (For PolarFire SoC FPGA Only) was added. • Information about 4.3 User Reset Generation Scheme was updated.
2.0	04/2020	<p>The following is a summary of the changes made in this revision.</p> <ul style="list-style-type: none"> • Information about 2.3 Design and Memory Initialization was updated. • Information about 2.3.5 How To Set Up Design and Memory Initialization was added. • Information about 4.3 User Reset Generation Scheme was added.
1.0	—	The first publication of this document.

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